



Committed to Customer Success



2024 Mobile Computing Solutions Product Selection Guide

www.nexcom.com



About NEXCOM

Mobile Computing Solutions

Founded in 1992, NEXCOM is committed to being your trustworthy partner in building the intelligent business. NEXCOM makes the difference by utilizing its industrial computing experience, a highly talented R&D team, strong world-class ODM services, and rapid support to customers. NEXCOM has worldwide customers from more than 50 countries and we never stop growth with our business partners. As we accelerate towards the future, NEXCOM has been playing an important role in bringing intelligence to transportation.

NEXCOM's Mobile Computing Solutions (MCS) has extended and developed many products for use in AI, 5G, and safety related applications. We're creating a safer working environment and saving operational costs through improvements in logistics for more efficient fleet management. Through the application and development of 5G, a better internet experience can be realized. We support our business partners to further promote edge AI computing for ADAS, AMR, and autonomous driving.

We focus on developing practical technologies, and constant growth brings us many advantages in the automotive sphere:

- Superior power designed for uninterrupted operations
- Smart and effective patented designs, resistant to very extreme environments
- Various communication module options (LoRa, V2X, NB-IoT, LTE, 5G NR, Wi-Fi 6/6E)

- Modular designs for the ease of maintenance
- Customized firmware and specialized ODM hardware solutions

NEXCOM has the passion, hope and dedication to keep moving forward making daily lives better through innovation. NEXCOM is forging ahead into the future and making it a success with our business partners!

Always Moving Forward



Our Core Competencies -

Building a Foundation for Interconnected IoV and Value-Added Innovation



Vehicle Mount Computer
VMC 2020



Railway Computer
aROK 5510

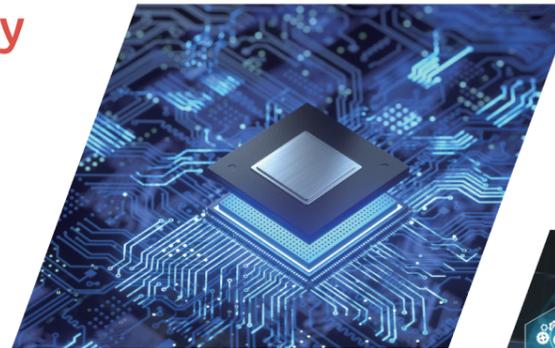


Railway Computer
aROK 8110

Premium Computing Design Capability

Computing power drives vehicle applications, which is why NEXCOM offers a wide range of computing platforms to meet different vehicle needs

- RISC platform (NXP i.MX6, i.MX8, Rockchip, TI)
- Intel Atom® platform (Bay Trail, Apollo Lake, Elkhart Lake, Alder Lake-N)
- Intel® Core™ i platform (Core i 8th, 9th, 11th, 12th, 13th Gen)
- Intel® high-end Xeon® platform
- NVIDIA® Jetson TX2, Xavier™ NX, Orin™ NX, AGX Orin™ integrated
- Over 20 years of experience in designing rugged devices and vehicle/railway computers



RF Communication Expansion

For the array of wireless usage cases, NEXCOM specializes in RF communication expansion, providing a comprehensive series of proprietary mini-PCIe/M.2 modules, allow users maximum flexibility in optimizing vehicle configurations

- GNSS (RTK, Dead reckoning)
- NB-IoT, 4G LTE, 5G NR
- DSRC/C-V2X, LoRa
- Wi-Fi 6/6E



Software Solutions

- SDK (API, programming guide, demo AP) supports for Linux, Android and Windows OS
- BSP (bootloader, kernel driver, OS (Android, Yocto, Ubuntu))
- MCU (customized MCU firmware for small quantities)
- BIOS (customized BIOS for small quantities)
- Secure System Development (TPM, Secure Boot, Boot Guard)



Reliability Quality

- Fanless design and IP67 protection for extreme environmental conditions
- IK08 impact resistance rating on external mechanics
- Meets CISPR25 standard
- Vehicle (E mark) and railway (EN50155, EN45545-2) certifications
- CE EMC (Electromagnetic Compatibility) and FCC conducted and radiated emissions certifications
- Supporting more certifications (Safety, RED, LVD, MIL-STD-810, etc.)

OEM/ODM Services

- Over 20 years of experience in industrial-grade computer design and manufacturing
- Seasoned design capabilities in customized system and software integration
- Certificated, 100%-owned manufacturing facilities in Taiwan
- Expertise in mobile transport technologies, with vertical domain know-how
- Acceptance of small to medium quantities, with fast time-to-market delivery



Specialization in AI Technology

- Specialize in NVIDIA® (GeForce/Quadro, PCIe x16/MXM, Jetson), Google Coral (M.2, mini-PCIe), and Hailo AI accelerators (M.2, mini-PCIe, onboard)
- Support partners to drive deeper customer engagement in AI + mobile edge computing applications
- Provide edge processing and AI capabilities to software partners/developers to innovate and create new business models



Our Product Portfolio



Product Series

- Edge AI Telematics Solution
- Vehicle Telematics Computer
- Railway Computer
- Vehicle Mount Computer
- Modular Vehicle Computer System
- Vehicle Mount Display
- In-Vehicle Networking
- In-Vehicle HDMI Extender over IP



ATC Series

Advanced Telematics Computer w/ GPU

- Designed for AI applications: ANPR, video analytics
- Selected NVIDIA GPU, MXM, Google TPU, and Hailo module add-ons
- 5G/LTE, Wi-Fi 6/6E, BT, CAN/OBD, GNSS + DR, PoE, and multi-SIM integration



VTC Series

In-Vehicle Telematics Computer

- General purpose, high-performance telematics computer
- 5G/LTE, Wi-Fi 6/6E, BT, CAN/OBD, GNSS + DR, PoE, and multi-SIM integration
- IP65/67 ingress protection
- Power management
- Backup battery kit



nROK/aROK/vROK Series

Railway Computer

- Box/Panel PC with fanless and rugged design
- 5G/LTE, Wi-Fi 6/6E, BT, CAN/OBD, GNSS + DR, PoE, and multi-SIM integration
- Optional isolated 24~110VDC power input
- EN50155 & EN45545-2 certifications



MVS Series

Modular Vehicle Computer Systems

- Modular CPU board + I/O board + expandable I/O board
- Flexible integration of LTE, Wi-Fi, BT, PoE, and other I/Os
- Easy customization of different I/O interfaces, with quick re-spins for faster time-to-market



VMC Series

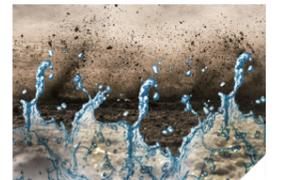
Rugged Vehicle Terminal

- Driver's operational display
- Designed for outdoor applications
- Full IP65 certification
- IK08-rated screens
- Vibration-, shock-, dust-, and water-resistant
- 5G/LTE, Wi-Fi 6/6E, CAN/OBD, GNSS + DR



PoE/10G LAN and RTSP Solutions

- Extends Full HD HDMI over IP for Passenger Infotainment Systems
- Design for video surveillance and AI video analytics applications
- Comply with 802.3af/at with RJ45 or M12 connector (D, X-coded)
- Mobile PoE switch and 10G PoE cards



Premium Solutions

- IP65/IP67 protection against water and dust
- IK ratings protection provided by panel PC against external mechanical impacts to display
- Performing conformal coating protection against moisture, dust and chemicals



2024 New Products



ATC 3750-IP7-6C/WI6CR

NVIDIA® Jetson AGX™ Orin, In-vehicle/Rail Performance Edge AI Computing

- Up to 200/275 TOPS of AI computing power, JetPack 5.1.1
- 6 PoE+ & 2 CANBus for CAM/LiDAR/Radar sensors, one selectable 10GbE
- Rugged, fanless and IP67 rated
- Support GNSS/LTE/5G NR & Wi-Fi 5/6 expansion modules
- CE/FCC, UKCA, E-mark/ EN50155, EN45545-2 Certified



ATC 3750-IP7-8M/WI8MR

NVIDIA® Jetson AGX™ Orin, In-vehicle/Rail Performance Edge AI Computing

- Up to 200/275 TOPS of AI computing power, JetPack 5.1.1
- 2.5GbE, 8 GMSL2 & 2 CANBus for CAM/LiDAR/Radar sensors
- Rugged, fanless and IP67 rated
- Support GNSS/LTE/5G NR & Wi-Fi 5/6 expansion modules
- CE/FCC, UKCA, E-mark/ EN50155, EN45545-2 Certified



ATC 3750-6C/A6CR

NVIDIA® Jetson AGX™ Orin, In-vehicle/Rail Performance Edge AI Computing

- Up to 200/275 TOPS of AI computing power, JetPack 5.1.1
- 6 PoE+ & 2 CANBus for CAM/LiDAR/Radar sensors, one selectable 10GbE
- Rugged, fanless
- Support GNSS/LTE/5G NR & Wi-Fi 5/6 expansion modules
- CE/FCC, UKCA, E-mark/ EN50155, EN45545-2, E13 Certified



VMC 320

10.1" Rugged Vehicle Mount Computer with Projected Capacitive Touch Screen

- Built-in NXP i.MX 8M Plus low-power processor, 4-core
- 10.1" 1280 x 800 resolution TFT LCD with projected capacitive touch screen
- Touch panel cover thickness 3mm for IK08 protection
- HDMI output for 2nd display
- Wide range DC input 9V ~ 60V



VMC 3030

10.1" Rugged Vehicle Mount Computer with Projected Capacitive Touch Screen

- Built-in Intel Atom® x7433RE processor, 4-core
- 10.1" 1280 x 800 resolution TFT LCD with projected capacitive touch screen
- Touch panel cover thickness 3mm for IK08 protection
- HDMI output for 2nd display
- Wide range DC input 9V ~ 60V



nROK 7270-A/AC4

Fanless Rolling Stock Computer with 12/13th Gen Intel® Core™ CPU

- Fanless, compact and rugged design
- Designed with DDR5, excellent memory bandwidth, lower latency
- 2 x 2.5" SSD for data integrity (compatible with 15mm disk)
- 5G/Wi-Fi, PoE, 10GbE, daughter board expansion support
- 4 x Independent 100/1000/2500 Mbps PoE 802.3af/at, total 60W (nROK 7270-AC4)



nROK 7271-WI/WIC4

Fanless Rolling Stock Computer with 12/13th Gen Intel® Core™ i CPU

- Designed with DDR5, excellent memory bandwidth, lower latency
- 2 x 2.5" SSD for data integrity (compatible with 15mm disk)
- 5G/Wi-Fi, PoE, 10GbE, daughter board expansion support
- 4 x Independent 100/1000/2500 Mbps PoE 802.3af/at, total 60W/30W (nROK 7271-WIC4)
- Wide voltage input 24~110VDC (w/ isolation). Optional up to 3-sec protection against temporary voltage dips



VTC 1920

Fanless In-vehicle Telematics Computer

- Intel® x7211RE quad-core processor (codenamed Amston Lake)
- HDMI output and 2.5GbE LAN ports
- Built-in 1 x isolated CAN FD
- Three expansion slots for 5G NR, LTE, Wi-Fi 6E
- Wide range DC input from 9~36V



VTC 6231/6231-IP

Fanless In-vehicle Telematics Computer

- Intel® x7433RE quad-core processor (codenamed Amston Lake)
- Triple display outputs and dual 2.5GbE LAN ports
- Built-in 1 x isolated CAN FD
- Five expansion slots for 5G NR, LTE, Wi-Fi 6E
- Full IP65 protection (VTC6231-IP)



VTK-SCAP

Smart UPS with Supercap for Vehicle & Railway

- High capacity supercapacitor for stable system operation
- 9~60V Wide Voltage Input
- 24V@8A max (up to 200W) power output
- Expandable Design (master/slave)
- Operating Temperature: -35~80°C

Industrial Edge AI Telematics Computer

ATC/aROK Series Brief Product Introduction

Product Description

AI has become an essential component of automated vehicle technologies. With built-in state of the art AI accelerator, ATC and aROK series are expertise for edge AI in-vehicle/railway applications. Besides, ATC/

aROK features with extreme wide-range operating temperature, military standard anti-vibration/shock and dust/water proof IP67 rating making it constantly perform 100% workload in harsh environments.

- NVIDIA® Jetson SOM, Quadro MXM/PCIe x16 AI accelerator support
- 5G/LTE, Wi-Fi 6/6E, BT, PoE, CAN function support

- EN50155 & E-Mark certification
- Optional railway isolated power input

Application

ATC: ADAS, ANPR, AMR, autonomous driving

aROK: Pantograph inspection, track obstacle inspection, traffic sign recognition

Product Highlight



Edge AI, inference accelerator



Sturdy system with securing cards/SOM for OHV and train



Strong ingress protection, IP65/IP67



MIPI SerDes solution support

Model	aROK 5510	aROK 8110
System		
CPU	Intel® Coffee Lake S/ Refresh Core™/Xeon®	Intel® Coffee Lake S/ Refresh Core™/Xeon®
Chipset	Intel® C246	Intel® C246
Fan/Fanless	Fan (fan-kit pre-installed)	Fan (fan-kit pre-installed)
Memory	4 x DDR4 2666 SO-DIMM, up to 32GB + 32GB + 32GB + 32GB	2 x DDR4 2666 SO-DIMM, up to 32GB + 32GB
Storage	6 x 2.5" SATA SSD (removable, 9.5mm)	4 x 2.5" SATA 3.0 SSD/HDD (removable, 15mm), or 3 x 2.5" SATA 3.0 SSD/HDD + 2 x M.2 2280/2242/2260 Key M NVMe SSD (PCIe 3.0 x2), or 3 x 2.5" SATA 3.0 SSD/HDD + 1 x U.2 NVMe SSD (PCIe 3.0 x2)
Second Storage	1 x mSATA. 1 x M.2 2280/2242/2260 Key M NVMe SSD (PCIe 3.0 x4). 1 x Removable SD 3.0	1 x CFast (removable)
GPU/VPU/TPU Coprocessor	One PCIe 3.0 x16 lane for optional NVIDIA Graphics card (100W)	One PCIe 3.0 x16 lane for optional NVIDIA Graphics card (350W)
Video Out	1 x VGA, 1 x HDMI	1 x VGA, 1 x HDMI
Audio	1 x Mic-in, 2 x Line-out	1 x Mic-in, 1 x Line-out
Ethernet	2 x Intel® 10/100/1000 (M12, X-coded). 2 x 10GbE SFP+ card (optional)	2 x Intel® 10/100/1000 (M12, X-coded)
PoE	4 x M12 GbE independent (802.3af/at). Total 60W (optional)	Up to 3 x GEM640 card (optional), each card with 4 x M12 Intel® GbE (w/ 802.3af/at). Total 60W+60W+60W
I/O Interface		
USB	2 x USB 2.0, 3 x USB 3.2 (Gen2), 1 x USB 3.2 (Gen1)	2 x USB 2.0, 3 x USB 3.2 (Gen2), 1 x USB 2.0
COM	2 x RS-232 (Full), 1 x RS232 (Full)/422/485. (w/ isolation)	4 x RS232 (Full)/422/485. (w/ isolation)
DIO	4 x DI, 4 x DO (w/ isolation)	4 x DI, 4 x DO (w/ isolation)
CAN Bus	1 x CAN Bus 2.0B (w/ isolation)	1 x CAN Bus 2.0B (w/ isolation)
SIM Socket	8 (BOM option up to 10, eSIM BOM optional)	4 (eSIM BOM optional)
DC Output	N/A	N/A
MIPI Interface	N/A	N/A
WWAN	4 (BOM option up to 5)	2
Expansion		
mini-PCIe Socket	- 1 x (USB 2.0, PCIe 3.0) - 1 x (USB 2.0, PCIe 3.0). - BOM option to 1 x mini-PCIe (USB 2.0) for LTE - 1 x (USB 2.0) for LTE. BOM option to 1 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen1)) for LTE/5G.	- 1 x (USB 2.0, PCIe 2.0) - 1 x (USB 2.0) for LTE. - BOM option to 1 x M.2 3042 Key B (USB 2.0) for LTE
M.2 Socket	3 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen2)) for LTE/5G	1 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen2)) for LTE/5G
Expansion PCIe Slot	- 1 x PCIe 3.0 x16	- 1 x PCIe 3.0 x16 - 3 x PCIe 3.0 x4
GNSS	VIOB-GPS-02 module (u-blox NEO-M8N)	VIOB-GPS-02 module (u-blox NEO-M8N)
Power Environment		
Power Input	DC 24/110V (w/ isolation)	DC 24/36V (w/o isolation)
Ingress Protection	N/A	N/A
Certification	CE, FCC Class A, UKCA, EN50155	CE, FCC Class A, UKCA, EN50155
Operating Temperature	-40°C to 70°C (OT4)	-40°C to 70°C (OT4)
Others		
TPM	TPM 2.0	TPM 2.0
OS	Win 10/11, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)
Dimensions (mm)	483 x 400 x 95	215 x 205 x 385



Industrial Edge AI Telematics Computer

Model				
	ATC 8010	ATC 8010-F	ATC 8110	ATC 8110-F
System				
CPU	Intel® Coffee Lake S/ Refresh Core™/Xeon®	Intel® Coffee Lake S/Refresh Core™/Xeon®	Intel® Coffee Lake S/ Refresh Core™/Xeon®	Intel® Coffee Lake S/ Refresh Core™/Xeon®
Chipset	Intel® Q370	Intel® Q370	Intel® C246	Intel® C246
Fan/Fanless	Fanless	Fan (fan-kit pre-installed)	Fanless	Fan (fan-kit pre-installed)
Memory	2 x DDR4 2400/2666 SO-DIMM, up to 32GB + 32GB	2 x DDR4 2400/2666 SO-DIMM, up to 32GB + 32GB	2 x DDR4 2400/2666 SO-DIMM, up to 32GB + 32GB	2 x DDR4 2400/2666 SO-DIMM, up to 32GB + 32GB
Storage	2 x 2.5" SATA 3.0 SSD (removable, 15mm)	2 x 2.5" SATA 3.0 SSD (removable, 15mm)	3 x 2.5" SATA 3.0 SSD/HDD (removable, 15mm) or 2 x 2.5" SATA 3.0 SSD/HDD + 1 x 2.5" U.2/NVMe M.2 2280	3 x 2.5" SATA 3.0 SSD/HDD (removable, 15mm) or 2 x 2.5" SATA 3.0 SSD/HDD + 1 x 2.5" U.2/NVMe M.2 2280
Second Storage	2 x mSATA (occupied mini-PCIe socket)	2 x mSATA (occupied mini-PCIe socket)	1 x CFast (removable)	1 x CFast (removable)
GPU/VPU/TPU Coprocessor	NVIDIA Quadro® MXM module (RTX A1000/RTX A2000)	NVIDIA Quadro® MXM module, Quadro (RTX A4500)	One 3-slot width PCIe 3.0 x16 lane for optional NVIDIA Graphics card	One 3-slot width PCIe 3.0 x16 lane for optional NVIDIA Graphics card
Video Out	1 x VGA, * 5 x HDMI, 1 x ultraONE+	1 x VGA, * 5 x HDMI, 1 x ultraONE+	1 x VGA, 1 x HDMI	1 x VGA, 1 x HDMI
Audio	1 x Mic-in, 1 x Line-out	1 x Mic-in, 1 x Line-out	1 x Mic-in, 1 x Line-out	2 x Mic-in, 2 x Line-out
Ethernet	1 x Intel® 10/100/1000	1 x Intel® 10/100/1000	2 x Intel® 10/100/1000	2 x Intel® 10/100/1000
PoE	8 x Independent Intel® 10/100/1000 (w/ 802.3af/at). Total 60W	8 x Independent Intel® 10/100/1000 (w/ 802.3af/at). Total 60W	N/A	N/A
USB	6 x USB 3.2 (Gen2)	6 x USB 3.2 (Gen2)	5 x USB 3.2 (Gen2), 1 x USB2.0	5 x USB 3.2 (Gen2), 1 x USB2.0
COM	2 x RS232 (Full), 1 x RS232 (Full)/422/485	2 x RS232 (Full), 1 x RS232 (Full)/422/485	4 x RS232 (Full)/422/485	4 x RS232 (Full)/422/485
DIO	4 x DI, 4 x DO	4 x DI, 4 x DO	4 x DI (w/ isolation) 4 x DO (w/ isolation)	4 x DI (w/ isolation) 4 x DO (w/ isolation)
CAN Bus	1 x CAN Bus 2.0B (w/ isolation)	1 x CAN Bus 2.0B (w/ isolation)	1 x CAN Bus 2.0B (w/ isolation)	1 x CAN Bus 2.0B (w/ isolation)
SIM Socket	3 (eSIM BOM optional)	3 (eSIM BOM optional)	4 (eSIM BOM optional)	4 (eSIM BOM optional)
DC Output	12V (2A)	12V (2A)	12V (2A)	12V (2A)
MIPI Interface	N/A	N/A	N/A	N/A
WWAN	2	2	2	2
mini-PCIe Socket	- 1 x (USB 2.0) for LTE - 1 x (USB 2.0, PCIe 3.0/SATA 3.0) - 1 x (USB 2.0, PCIe 3.0/SATA 3.0)	- 1 x (USB 2.0) for LTE - 1 x (USB 2.0, PCIe 3.0/SATA 3.0) - 1 x (USB 2.0, PCIe 3.0/SATA 3.0)	- 1 x (USB 2.0) for LTE - 1 x (USB 2.0, PCIe 2.0)	- 1 x (USB 2.0) for LTE - 1 x (USB 2.0, PCIe 2.0)
M.2 Socket	1 x M.2 3042 Key B (USB 2.0, USB 3.2 (Gen1)) for LTE/5G	1 x M.2 3042 Key B (USB 2.0, USB 3.2 (Gen1)) for LTE/5G	1 x M.2 3042/3052 Key B (USB 2.0, USB 3.2 (Gen1)) for LTE/5G	1 x M.2 3042/3052 Key B (USB 2.0, USB 3.2 (Gen1)) for LTE/5G
Expansion PCIe Slot	N/A	N/A	- 1 x PCIe 3.0 x16, - 1 x PCIe 3.0 x4 + proprietary, - 1 x PCIe 3.0 x4	1 x PCIe x16, 1 x PCIe x4 + proprietary, 1 x PCIe x4
GNSS	VIOB-GPS-02 module (u-blox NEO-M8N)	VIOB-GPS-02 module (u-blox NEO-M8N)	VIOB-GPS-02 module (u-blox NEO-M8N)	VIOB-GPS-02 module (u-blox NEO-M8N)
Power				
Power Input	DC 9V to 36V	DC 9V to 36V	DC 9V to 36V	DC 9V to 36V
Environment				
Ingress Protection	N/A	N/A	N/A	N/A
Certification	CE, FCC Class A, UKCA, E13	CE, FCC Class A, UKCA, E13	CE, FCC Class A, UKCA, E13	CE, FCC Class A, UKCA, E13
Operating Temperature	-30°C to 60°C	-30°C to 60°C	-30°C to 60°C	-30°C to 60°C
TPM	TPM 2.0	TPM 2.0	TPM 2.0	TPM 2.0
Others				
OS	Win 10/11, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)
Dimensions (mm)	260 x 259.7 x 90.1	260 x 259.7 x 99 (w/ fan kit)	191.2 x 176 x 350	207.4 x 176 x 350 (w/ fan kit)



Based on different MXM for ATC 8010 and ATC 8010-F, the quantity will be different.

Product appearance and specifications are subject to change without notice.

Model				
	ATC 3520-IP7-4C	ATC3520-IP7-AI4CR (Rail)	ATC 3530-IP7-4M	ATC 3530-IP7-4C
System				
CPU	NVIDIA® Jetson Orin™ Nano	NVIDIA® Jetson Orin™ Nano	NVIDIA® Jetson Xavier™ NX	NVIDIA® Jetson Xavier™ NX
Chipset	N/A	N/A	N/A	N/A
Fan/Fanless	Fanless	Fanless	Fanless	Fanless
Memory	Onboard LPDDR5, 4GB	Onboard LPDDR5, 4GB	Onboard LPDDR4, 8GB/16GB	Onboard LPDDR4, 8GB/16GB
Storage	N/A	N/A	16GB eMMC 5.1	16GB eMMC 5.1
Second Storage	1 x 128GB M.2 2280 Key M NVMe SSD (PCIe 4.0 x4)	1 x 128GB M.2 2280 Key M NVMe SSD (PCIe 4.0 x4)	1 x Removable microSD, 1 x M.2 2280 Key M NVMe SSD (PCIe 3.0 x4)	1 x Removable microSD, 1 x M.2 2280 Key M NVMe SSD (PCIe 3.0 x4)
GPU/VPU/TPU Coprocessor	NVIDIA® Ampere 512/1024-core, 16/32 Tensor-core integrated GPU @625MHz	NVIDIA® Ampere 512/1024-core, 16/32 Tensor-core integrated GPU @625MHz	NVIDIA® Volta 384-core, 48 Tensor-core integrated GPU @1.1GHz	NVIDIA® Volta 384-core, 48 Tensor-core integrated GPU @1.1GHz
Video Out	1 x HDMI	1 x HDMI	1 x HDMI	1 x HDMI
Audio	N/A	N/A	N/A	N/A
Ethernet	1 x Intel® 10/100/1000 (M12 X-coded)	1 x Intel® 10/100/1000 (M12 X-coded)	2 x Intel® 10/100/1000 (M12 X-coded)	1 x Intel® 10/100/1000 (M12 X-coded)
PoE	4 x GbE M12 X-coded (802.3af/at). Total 30W	4 x GbE M12 X-coded (802.3af/at). Total 30W	Option for PoE (w/ 802.3af/at). Total 30W	4 x GbE M12 X-coded (802.3af/at). Total 30W
USB	2 x USB 3.2 (Gen1), 2 x USB 2.0 (reserved), 1 x OTG	2 x USB 3.2 (Gen1), 2 x USB 2.0 (reserved), 1 x OTG	2 x USB 3.2 (Gen1), 2 x USB 2.0 (reserved), 1 x OTG	2 x USB 3.2 (Gen1), 2 x USB 2.0 (reserved), 1 x OTG
COM	2 x RS232, 1 x Console			
DIO	4 x DI, 4 x DO (w/ isolation)	4 x DI, 4 x DO (w/ isolation)	4 x DI, 4 x DO (w/ isolation)	4 x DI, 4 x DO (w/ isolation)
CAN Bus	1 x CAN Bus 2.0B (w/ isolation)			
SIM Socket	2	2	2	2
DC Output	N/A	N/A	N/A	N/A
MIPI Interface	N/A	N/A	4 (Thin, V-by-One HS)	N/A
WWAN	1	1	1	1
mini-PCIe Socket	1 x (USB 2.0, PCIe 4.0)	1 x (USB 2.0, PCIe 4.0)	1 x (USB 2.0, PCIe 3.0)	1 x (USB 2.0, PCIe 3.0)
M.2 Socket	1 x M.2 3042/3052 Key B (USB 2.0, USB 3.2 (Gen1)) for LTE/5G	1 x M.2 3042/3052 Key B (USB 2.0, USB 3.2 (Gen1)) for LTE/5G	1 x M.2 3042/3052 Key B (USB 2.0, USB 3.2 (Gen1)) for LTE/5G	1 x M.2 3042/3052 Key B (USB 2.0, USB 3.2 (Gen1)) for LTE/5G
Expansion PCIe Slot	N/A	N/A	N/A	N/A
GNSS	VIOB-GPS-06 module (u-blox NEO-M9N)	VIOB-GPS-06 module (u-blox NEO-M9N)	VIOB-GPS-02 module (u-blox NEO-M8N)	VIOB-GPS-02 module (u-blox NEO-M8N)
Power				
Power Input	DC 9V to 36V	DC 24V w/ Power isolation box (PWA10-01) installed	DC 9V to 36V	DC 9V to 36V
Environment				
Ingress Protection	IP67	IP67	IP67	IP67
Certification	CE, FCC Class A, UKCA	CE, FCC Class A, UKCA, EN50121-3-2	CE, FCC Class A, UKCA, E13	CE, FCC Class A, UKCA, E13
Operating Temperature	-30°C to 70°C	-30°C to 70°C (OT3)	-30°C to 70°C	-30°C to 70°C
TPM	N/A	N/A	N/A	N/A
Others				
OS	Nexcom Accelerator Linux (NAL) w/ JetPack 5.1.1, Ubuntu 20.04 @kernel 5.10	Nexcom Accelerator Linux (NAL) w/ JetPack 5.1.1, Ubuntu 20.04 @kernel 5.10	Nexcom Accelerator Linux (NAL) w/ JetPack 4.6, Ubuntu 18.04 @kernel 4.9.140	Nexcom Accelerator Linux (NAL) w/ JetPack 4.6, Ubuntu 18.04 @kernel 4.9.140
Dimensions (mm)	213.0 x 167.0 x 82.8	213.0 x 167.0 x 122.8	213.0 x 167.0 x 82.8	213.0 x 167.0 x 82.8



Product appearance and specifications are subject to change without notice.

Industrial Edge AI Telematics Computer

Industrial Edge AI Telematics Computer

Industrial Edge AI Telematics Computer

Model	 NEW ATC 3540-IP7-4C	 NEW ATC 3540-IP7-AI4CR (Rail)	 NEW ATC 3750-6C	 NEW ATC 3750-A6CR (Rail)
System	CPU: NVIDIA® Jetson Orin™ NX Chipset: N/A Fan/Fanless: Fanless Memory: Onboard LPDDR5, 8GB/16GB Storage: N/A Second Storage: 1 x 128GB M.2 2280 Key M NVMe SSD (PCIe 4.0 x4)	CPU: NVIDIA® Jetson Orin™ NX Chipset: N/A Fan/Fanless: Fanless Memory: Onboard LPDDR5, 8GB/16GB Storage: N/A Second Storage: 1 x 128GB M.2 2280 Key M NVMe SSD (PCIe 4.0 x4)	CPU: NVIDIA® Jetson AGX™ Orin Chipset: N/A Fan/Fanless: Fanless Memory: Onboard LPDDR5, 32GB/64GB Storage: 64GB eMMC 5.1 Second Storage: "1 x Removable microSD "1 x M.2 2280 Key M NVMe SSD (PCIe 4.0 x4)"	CPU: NVIDIA® Jetson AGX™ Orin Chipset: N/A Fan/Fanless: Fanless Memory: Onboard LPDDR5, 32GB/64GB Storage: 64GB eMMC 5.1 Second Storage: "1 x Removable microSD "1 x M.2 2280 Key M NVMe SSD (PCIe 4.0 x4)"
I/O Interface	GPU/VPU/TPU Coprocessor: NVIDIA® Ampere 1024-core, 32 Tensor-core integrated GPU @918MHz Video Out: 1 x HDMI Audio: N/A Ethernet: 1 x Intel® 10/100/1000 (M12 X-coded) PoE: 4 x GbE M12 X-coded (802.3af/at). Total 30W USB: 2 x USB 3.2 (Gen1), 2 x USB 2.0 (reserved), 1 x OTG COM: 2 x RS232, 1 x Console DIO: 4 x DI, 4 x DO (w/ isolation) CAN Bus: 1 x CAN Bus 2.0B (w/ isolation) SIM Socket: 2 DC Output: N/A MIPI Interface: N/A WWAN: 1 mini-PCIe Socket: 1 x (USB 2.0, PCIe 4.0)	GPU/VPU/TPU Coprocessor: NVIDIA® Ampere 1024-core, 32 Tensor-core integrated GPU @918MHz Video Out: 1 x HDMI Audio: N/A Ethernet: 1 x Intel® 10/100/1000 (M12 X-coded) PoE: 4 x GbE M12 X-coded (802.3af/at). Total 30W USB: 2 x USB 3.2 (Gen1), 2 x USB 2.0 (reserved), 1 x OTG COM: 2 x RS232, 1 x Console DIO: 4 x DI, 4 x DO (w/ isolation) CAN Bus: 1 x CAN Bus 2.0B (w/ isolation) SIM Socket: 2 DC Output: N/A MIPI Interface: N/A WWAN: 1 mini-PCIe Socket: 1 x (USB 2.0, PCIe 4.0)	GPU/VPU/TPU Coprocessor: NVIDIA® Ampere 1792/2048-core, 56/64 Tensor-core integrated GPU @939MHz/1.3GHz Video Out: 1 x HDMI Audio: N/A Ethernet: 1 x 10GbE RJ45 (option) PoE: 6 x GbE RJ45 (802.3af/at). Total 80W USB: 2 x USB 3.2 (Gen2), 1 x OTG COM: 2 x RS232, 1 x Console DIO: 4 x DI, 4 x DO (w/ isolation) CAN Bus: 2 x CAN FD (w/ isolation) SIM Socket: 2 DC Output: N/A MIPI Interface: N/A WWAN: 1 mini-PCIe Socket: 1 x (USB 2.0, PCIe 4.0)	GPU/VPU/TPU Coprocessor: NVIDIA® Ampere 1792/2048-core, 56/64 Tensor-core integrated GPU @939MHz/1.3GHz Video Out: 1 x HDMI Audio: N/A Ethernet: 1 x 10GbE M12 X-coded (option) PoE: 6 x GbE M12 X-coded (802.3af/at). Total 80W USB: 2 x USB 3.2 (Gen2), 1 x OTG COM: 2 x RS232, 1 x Console DIO: 4 x DI, 4 x DO (w/ isolation) CAN Bus: 2 x CAN FD (w/ isolation) SIM Socket: 2 DC Output: N/A MIPI Interface: N/A WWAN: 1 mini-PCIe Socket: 1 x (USB 2.0, PCIe 4.0)
Expansion	M.2 Socket: - 1 x M.2 3042/3052 Key B (USB 2.0, USB 3.2 (Gen1)) for LTE/5G Expansion PCIe Slot: N/A GNSS: VIOB-GPS-06 module (u-blox NEO-M9N)	M.2 Socket: - 1 x M.2 3042/3052 Key B (USB 2.0, USB 3.2 (Gen1)) for LTE/5G Expansion PCIe Slot: N/A GNSS: VIOB-GPS-06 module (u-blox NEO-M9N)	M.2 Socket: - 1 x M.2 3042/3052 Key B (USB 2.0, USB 3.2 (Gen2)) for LTE/5G - 1 x M.2 3030 Key E (PCIe4.0, USB2.0) Expansion PCIe Slot: N/A GNSS: VIOB-GPS-06 module (u-blox NEO-M9N)	M.2 Socket: - 1 x M.2 3042/3052 Key B (USB 2.0, USB 3.2 (Gen2)) for LTE/5G - 1 x M.2 3030 Key E (PCIe4.0, USB2.0) Expansion PCIe Slot: N/A GNSS: VIOB-GPS-06 module (u-blox NEO-M9N)
Environment	Power Input: DC 9V to 36V Ingress Protection: IP67 Certification: CE, FCC Class A, UKCA, E13 Operating Temperature: -30°C to 70°C TPM: N/A	Power Input: DC 24V w/ Power isolation box (PWA10-01) installed Ingress Protection: IP67 Certification: CE, FCC Class A, UKCA, EN50155 Operating Temperature: -30°C to 70°C (OT3) TPM: N/A	Power Input: DC 9V to 36V Ingress Protection: IP50 Certification: CE, FCC Class A, UKCA, E13 Operating Temperature: -25°C to 70°C TPM: N/A	Power Input: DC 24V Power isolation box (PWA20-01) in option Ingress Protection: IP67 Certification: CE, FCC Class A, UKCA, EN50155, EN45545-2 Operating Temperature: -25°C to 70°C (OT3) TPM: N/A
Others	OS: Nexcom Accelerator Linux (NAL) w/ JetPack 5.1.1, Ubuntu 20.04 @kernel 5.10 Dimensions (mm): 213.0 x 167.0 x 82.8	OS: Nexcom Accelerator Linux (NAL) w/ JetPack 5.1.1, Ubuntu 20.04 @kernel 5.10 Dimensions (mm): 213.0 x 167.0 x 122.8	OS: Nexcom Accelerator Linux (NAL) w/ JetPack 5.1.1, Ubuntu 20.04 @Kernel 5.10 Dimensions (mm): 234.0 x 172.8 x 80.5	OS: Nexcom Accelerator Linux (NAL) w/ JetPack 5.1.1, Ubuntu 20.04 @Kernel 5.10 Dimensions (mm): 234.0 x 172.8 x 114.5 (w/ option power isolation box)



Model	 NEW ATC 3750-IP7-6C (In-vehicle/Rail)	 NEW ATC 3750-IP7-WI6CR (Rail)	 NEW ATC 3750-IP7-8M (In-vehicle/Rail)	 NEW ATC 3750-IP7-WI8MR (Rail)
System	CPU: NVIDIA® Jetson AGX™ Orin Chipset: N/A Fan/Fanless: Fanless Memory: Onboard LPDDR5, 32GB/64GB Storage: 64GB eMMC 5.1 Second Storage: 1 x Removable microSD 1 x M.2 2280 Key M NVMe SSD (PCIe 4.0 x4)	CPU: NVIDIA® Jetson AGX™ Orin Chipset: N/A Fan/Fanless: Fanless Memory: Onboard LPDDR5, 32GB/64GB Storage: 64GB eMMC 5.1 Second Storage: 1 x Removable microSD 1 x M.2 2280 Key M NVMe SSD (PCIe 4.0 x4)	CPU: NVIDIA® Jetson AGX™ Orin Chipset: N/A Fan/Fanless: Fanless Memory: Onboard LPDDR5, 32GB/64GB Storage: 64GB eMMC 5.1 Second Storage: 1 x Removable microSD 1 x M.2 2280 Key M NVMe SSD (PCIe 4.0 x4)	CPU: NVIDIA® Jetson AGX™ Orin Chipset: N/A Fan/Fanless: Fanless Memory: Onboard LPDDR5, 32GB/64GB Storage: 64GB eMMC 5.1 Second Storage: 1 x Removable microSD 1 x M.2 2280 Key M NVMe SSD (PCIe 4.0 x4)
I/O Interface	GPU/VPU/TPU Coprocessor: NVIDIA® Ampere 1792/2048-core, 56/64 Tensor-core integrated GPU @939MHz/1.3GHz Video Out: 1 x HDMI Audio: N/A Ethernet: 1 x 10GbE M12 X-coded (option) PoE: 6 x GbE M12 X-coded (802.3af/at). Total 80W USB: 2 x USB 3.2 (Gen2, M12 X-coded), 1 x OTG COM: 2 x RS232, 1 x Console DIO: 4 x DI, 4 x DO (w/ isolation) CAN Bus: 2 x CAN FD (w/ isolation) SIM Socket: 2 DC Output: 5V (2A) MIPI Interface: N/A WWAN: 1 mini-PCIe Socket: - 1 x (USB 2.0, PCIe 4.0)	GPU/VPU/TPU Coprocessor: NVIDIA® Ampere 1792/2048-core, 56/64 Tensor-core integrated GPU @939MHz/1.3GHz Video Out: 1 x HDMI Audio: N/A Ethernet: 1 x 10GbE M12 X-coded (option) PoE: 6 x GbE M12 X-coded (802.3af/at). Total 80W USB: 2 x USB 3.2 (Gen2, M12 X-coded), 1 x OTG COM: 2 x RS232, 1 x Console DIO: 4 x DI, 4 x DO (w/ isolation) CAN Bus: 2 x CAN FD (w/ isolation) SIM Socket: 2 DC Output: 5V (2A) MIPI Interface: N/A WWAN: 1 mini-PCIe Socket: - 1 x (USB 2.0, PCIe 4.0)	GPU/VPU/TPU Coprocessor: NVIDIA® Ampere 1792/2048-core, 56/64 Tensor-core integrated GPU @939MHz/1.3GHz Video Out: 1 x HDMI Audio: N/A Ethernet: 1 x Intel® 10/100/1000 (M12 X-coded) PoE: N/A USB: 2 x USB 3.2 (Gen2), 2 x USB2.0 (M12), 1 x OTG COM: 1 x RS232, 1 x RS232 /422/485, 1 x Console DIO: 4 x DI, 4 x DO CAN Bus: 2 x CAN FD (w/ isolation) SIM Socket: 2 DC Output: N/A MIPI Interface: 8 (GMSL2) WWAN: 1 mini-PCIe Socket: - 1 x (USB 2.0, PCIe 4.0)	GPU/VPU/TPU Coprocessor: NVIDIA® Ampere 1792/2048-core, 56/64 Tensor-core integrated GPU @939MHz/1.3GHz Video Out: 1 x HDMI Audio: N/A Ethernet: 1 x Intel® 10/100/1000 (M12 X-coded) PoE: N/A USB: 2 x USB 3.2 (Gen2), 2 x USB2.0 (M12), 1 x OTG COM: 1 x RS232, 1 x RS232 /422/485, 1 x Console DIO: 4 x DI, 4 x DO CAN Bus: 2 x CAN FD (w/ isolation) SIM Socket: 2 DC Output: N/A MIPI Interface: 8 (GMSL2) WWAN: 1 mini-PCIe Socket: - 1 x (USB 2.0, PCIe 4.0)
Expansion	M.2 Socket: - 1 x M.2 3042/3052 Key B (USB 2.0, USB 3.2 (Gen2)) for LTE/5G - 1 x M.2 3030 Key E (PCIe4.0, USB2.0) Expansion PCIe Slot: N/A GNSS: VIOB-GPS-07 module (u-blox NEO-M9N)	M.2 Socket: - 1 x M.2 3042/3052 Key B (USB 2.0, USB 3.2 (Gen2)) for LTE/5G - 1 x M.2 3030 Key E (PCIe4.0, USB2.0) Expansion PCIe Slot: N/A GNSS: VIOB-GPS-07 module (u-blox NEO-M9N)	M.2 Socket: - 1 x M.2 3042/3052 Key B (USB 2.0, USB 3.2 (Gen2)) for LTE/5G - 1 x M.2 3030 Key E (PCIe4.0, USB2.0) Expansion PCIe Slot: N/A GNSS: VIOB-GPS-07 module (u-blox NEO-M9N)	M.2 Socket: - 1 x M.2 3042/3052 Key B (USB 2.0, USB 3.2 (Gen2)) for LTE/5G - 1 x M.2 3030 Key E (PCIe4.0, USB2.0) Expansion PCIe Slot: N/A GNSS: VIOB-GPS-07 module (u-blox NEO-M9N)
Environment	Power Input: DC 9V to 36V/ 24V Rail Ingress Protection: IP67 Certification: CE, FCC Class A, UKCA, E13, EN50155 (OT3) Operating Temperature: -25°C to 70°C TPM: N/A	Power Input: DC 24V to 110V Ingress Protection: IP67 Certification: CE, FCC Class A, UKCA, EN50155, EN45545-2 Operating Temperature: -25°C to 70°C (OT3) TPM: N/A	Power Input: DC 9V to 36V/ 24V Rail Ingress Protection: IP67 Certification: CE, FCC Class A, UKCA, E13, EN50155 (OT3) Operating Temperature: -25°C to 70°C TPM: N/A	Power Input: DC 24V to 110V Ingress Protection: IP67 Certification: CE, FCC Class A, UKCA, EN50155, EN45545-2 Operating Temperature: -25°C to 70°C (OT3) TPM: N/A
Others	OS: Nexcom Accelerator Linux (NAL) w/ JetPack 5.1.1, Ubuntu 20.04 @Kernel 5.10 Dimensions (mm): 260.0 x 153.0 x 66.5	OS: Nexcom Accelerator Linux (NAL) w/ JetPack 5.1.1, Ubuntu 20.04 @Kernel 5.10 Dimensions (mm): 260.0 x 155.0 x 88.0	OS: Nexcom Accelerator Linux (NAL) w/ JetPack 5.1.1, Ubuntu 20.04 @Kernel 5.10 Dimensions (mm): 260.0 x 155.0 x 66.5	OS: Nexcom Accelerator Linux (NAL) w/ JetPack 5.1.1, Ubuntu 20.04 @Kernel 5.10 Dimensions (mm): 260.0 x 155.0 x 88.0



Based on different MXM for ATC 8010 and ATC 8010-F, the quantity will be different.

Vehicle Telematics Computer

VTC Series Brief Product Introduction

Product Description

VTC and MVS series are fanless embedded telematics system which can sustain in harsh environment, with rich I/O connectivity for external peripherals, and easy RF communication expansion. The modular design makes the

MVS series very flexible to adopt other expansion boards and thus extend I/O functions. Besides, we provide MUT (MCU Utility Tools) SDK for power management & control, which greatly reduces Time-To-Market.

-  5G/LTE, Wi-Fi 6/6E, BT, CAN/OBD module support
-  IP65/67 ingress protection

-  Ignition power management
-  AI accelerator module support

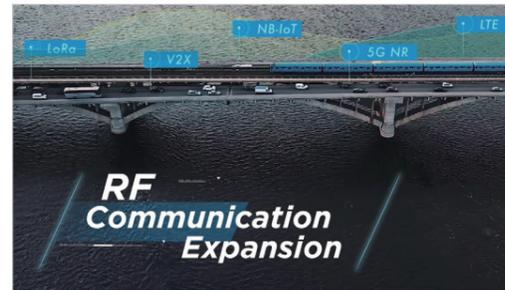
Application

- Fleet management
- Vehicle gateway
- Video surveillance
- Passenger information system
- Infotainment applications.

Product Highlight



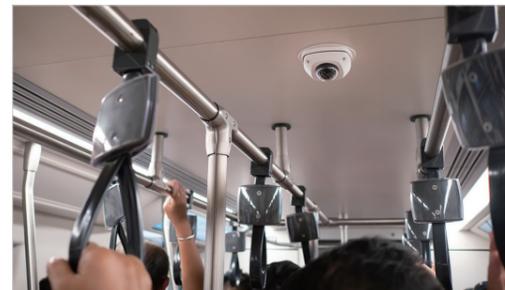
Rugged design for harsh environment



Flexible RF communication expansion



Dead reckoning & RTK precise positioning



802.3 af/at PoE+ support

Model			 Coming soon	 Coming soon
	VTC 210	VTC 1910-S	VTC 1920	VTC 1921-IP
System				
CPU	Rockchip RK3328	Intel Atom® E3815, 1-core, 1.46GHz	Intel Atom® x7211RE, 2-core, 1.0GHz	Intel Atom® x7211RE, 2-core, 1.0GHz
Chipset	N/A	N/A	N/A	N/A
Memory	DDR4 2GB onboard up to 4GB	1 x DDR3L 1333 SO-DIMM, 4GB (default) up to 8GB	1 x DDR4 3200 SO-DIMM, 4GB (default) up to 16GB, in-band ECC support	1 x DDR4 3200 SO-DIMM, 4GB (default) up to 16GB, in-band ECC support
Storage	eMMC 5.1, 16GB	1 x SATA 2.0 mSATA	1 x M.2 2242 Key M SSD (SATA 3.0)	1 x 2.5" SATA 3.0 SSD (9.5mm)
Second Storage	1 x Micro SD	1 x SATA DOM	1 x M.2 2280 Key M SSD (SATA 3.0)	1 x mSATA (occupied mini-PCIe socket)
Video Out	1 x HDMI	1 x VGA	1 x HDMI	1 x VGA, 1 x HDMI (optional)
Audio	N/A	1 x Mic-in, 1 x Line-out	1 x Mic-in, 1 x Line-out	1 x Mic-in, 1 x Line-out
Ethernet	2 x Intel® 10/100/1000 LAN Switch	1 x Intel® 10/100/1000	1 x Intel® 10/100/1000/2500	2 x Intel® 10/100/1000/2500
PoE	N/A	N/A	N/A	N/A
I/O Interface				
USB	1 x external USB 2.0 1 x internal USB 2.0 for WIFI	1 x USB 3.0, 1 x USB 2.0	2 x USB 3.2 (Gen 2)	1 x USB 3.2 (Gen 2), 1 x USB 2.0
COM	1 x RS232 (Full)	2 x RS232, 1 x RS485	2 x RS232, 1 x RS485	2 x RS232, 1 x RS485
DIO	N/A	3 x DI, 3 x DO	3 x DI, 3 x DO	4 x DI, 4 x DO
CAN Bus	N/A	1 x CAN Bus 2.0B	1 x CAN FD, 1 x CAN Bus 2.0B (w/ isolation)	1 x CAN FD, 1 x CAN Bus 2.0B (w/ isolation)
DC Output	N/A	N/A	N/A	N/A
SMBus	N/A	N/A	N/A	N/A
SIM Socket	1	2	2 (BOM optional up to 3, eSIM BOM optional)	2 (eSIM BOM optional)
Expansion				
WWAN	1	1	1 (BOM optional up to 2)	2
mini-PCIe Socket	N/A	- 1 x (PCIe 2.0/SATA 2.0) - 1 x (USB 2.0) for LTE	- 1 x (USB 2.0), BOM optional to 1 x M.2 3042/3052 Key B (USB 2.0) for LTE	- 1 x (USB 2.0, PCIe3.0/SATA 2.0)
M.2 Socket	- 1 x M.2 3042 Key B (USB 2.0, USB 3.2 (Gen1)) for LTE	N/A	- 1 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen 2)) for LTE/5G - 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0 x1)	- 1 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen 2)) for LTE/5G - 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0 x1)
GNSS	VI0B-GPS-06 module (u-blox NEO-M9N)	Onboard u-blox NEO-M8N	Onboard u-blox NEO-M9N	Onboard u-blox NEO-M9N
Power				
Power Input	DC 9V to 36V	DC 9V to 36V	DC 9V to 36V	DC 9V to 36V
Back Up Battery	N/A	N/A	N/A	N/A
Environment				
Ingress Protection	N/A	N/A	N/A	IP67
Certification	CE, FCC Class A, UKCA, E13	CE, FCC Class A, E13	CE, FCC Class A, E13	CE, FCC Class A, E13, EN50155
Operating Temperature	-20°C to 70°C	-40°C to 70°C	-40°C to 70°C	-40°C to 70°C
TPM	N/A	TPM 2.0	TPM 2.0	TPM 2.0
Others				
OS	Linux (Kernel 4.x)	WES 7, Win 7/8/ 10 Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)
Dimensions (mm)	130.0 x 100.0 x 31.0	130.0 x 120.0 x 32.0	130.0 x 120.0 x 32.0	185.0 x 167.0 x 56.5



Vehicle Telematics Computer

Model	 VTC 1921-C2SIP	 VTC 1911-IPK	 VTC 1011-C2K	 VTC 1011-C2VK
System				
CPU	Intel Atom® x7211RE, 2-core, 1.0GHz	Intel Atom® E3815, 1-core, 1.46GHz	Intel Atom® E3825, 2-core, 1.33GHz	Intel Atom® E3825, 2-core, 1.33GHz
Chipset	N/A	N/A	N/A	N/A
Memory	1 x DDR4 3200 SO-DIMM, 4GB (default) up to 16GB, in-band ECC support	1 x DDR3L 1333 SO-DIMM, 4GB (default) up to 8GB	1 x DDR3L 1333 SO-DIMM, 4GB (default) up to 8GB	1 x DDR3L 1333 SO-DIMM, 4GB (default) up to 8GB
Storage	1 x 2.5" SATA 3.0 SSD (9.5mm)	1 x SATA 2.0 mSATA	1 x 2.5" SATA 3.0 SSD (9.5mm)	1 x 2.5" SATA 3.0 SSD (9.5mm)
Second Storage	1 x mSATA (occupied mini-PCIe socket)	1 x 2.5" SSD (9.5mm) or 1 x SATA DOM	1 x mSATA (occupied mini-PCIe socket)	1 x mSATA (occupied mini-PCIe socket)
Video Out	1 x VGA	1 x VGA, 1 x HDMI (optional)	1 x VGA, 1 x HDMI	1 x VGA, 1 x HDMI, 1 x ultraONE+
Audio	1 x Mic-in, 1 x Line-out	1 x Mic-in, 1 x Line-out	1 x Mic-in, 1 x Line-out	1 x Mic-in, 1 x Line-out
Ethernet	2 x Intel® 10/100/1000/2500	2 x Intel® 10/100/1000	2 x Intel® 10/100/1000 (exclusion with PoE)	2 x Intel® 10/100/1000 (exclusion with PoE)
PoE	2 x Intel® 2.5GbE (w/ 802.3af/at). Total 10W	N/A	2 x Intel® 10/100/1000 (w/ 802.3af/at). Total 30W	2 x Intel® 10/100/1000 (w/ 802.3af/at). Total 30W
I/O Interface				
USB	1 x USB 3.2 (Gen 2), 1 x USB 2.0	1 x USB 2.0	2 x USB 2.0	2 x USB 2.0
COM	2 x RS232, 1 x RS485	2 x RS232, 1 x RS485	1 x RS232 (full), 1 x RS232/RS422/485	1 x RS232 (full), 1 x RS232/RS422/485
DIO	4 x DI, 4 x DO	3 x DI, 3 x DO	4 x DI, 4 x DO	4 x DI, 4 x DO
CAN Bus	1 x CAN FD, 1 x CAN Bus 2.0B (w/ isolation)	1 x CAN Bus 2.0B	1 x CAN Bus 2.0B	1 x CAN Bus 2.0B
DC Output	N/A	N/A	12V (2A)	12V (2A)
SMBus	N/A	N/A	1	1
SIM Socket	2 (eSIM BOM optional)	2	2	2
Expansion				
WWAN	2	1	1	1
mini-PCIe Socket	- 1 x (USB 2.0, PCIe 3.0/SATA 2.0)	- 1 x (USB 2.0, PCIe 2.0/SATA 2.0) - 1 x (USB 2.0) for LTE	- 1 x (USB 2.0, PCIe 2.0/SATA 2.0) - 1 x (USB 2.0) for LTE	- 1 x (USB 2.0, PCIe 2.0/SATA 2.0) - 1 x (USB 2.0) for LTE
M.2 Socket	1 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen 2)) for LTE/5G - 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0 x1)	N/A	N/A	N/A
GNSS	Onboard u-blox NEO-M9N	Onboard u-blox NEO-M8N	VIOB-GPS-02 module (u-blox NEO-M8N)	VIOB-GPS-02 module (u-blox NEO-M8N)
Power				
Power Input	DC 9V to 36V	DC 9V to 36V	DC 9V to 36V	DC 9V to 36V
Back Up Battery	N/A	N/A	N/A	N/A
Environment				
Ingress Protection	IP67	IP67	N/A	N/A
Certification	CE, FCC Class A, E13, EN50155	CE, FCC Class A, E13, EN50155	CE, FCC Class A, UKCA, E13	CE, FCC Class A, UKCA, E13
Operating Temperature	-40°C to 70°C	-40°C to 70°C	-40°C to 70°C (LAN mode) -40°C to 60°C (PoE mode)	-40°C to 70°C (LAN mode) -40°C to 60°C (PoE mode)
TPM	TPM 2.0	TPM 2.0	TPM 2.0	TPM 2.0
Others				
OS	Win 10/11, Linux (Kernel 4.x)	WES 7, Win 7/8/10 Linux (Kernel 4.x)	WES 7, Win 7/8/10 Linux (Kernel 4.x)	WES 7, Win 7/8/10 Linux (Kernel 4.x)
Dimensions (mm)	185.0 x 167.0 x 56.5	185.0 x 167.0 x 56.5	185.0 x 150.9 x 45.0	185.0 x 150.9 x 45.0



Model	 VTC 1020	 VTC 1020-PA	 VTC 1010
System			
CPU	Intel Atom® x5-E3930, 2-core, 1.3GHz	Intel Atom® x5-E3930, 2-core, 1.3GHz	Intel Atom® E3827, 2-core, 1.75GHz
Chipset	N/A	N/A	N/A
Memory	1 x DDR3L 1866 SO-DIMM, 4GB (default) up to 8GB	1 x DDR3L 1866 SO-DIMM, 4GB (default) up to 8GB	1 x DDR3L 1333 SO-DIMM, 4GB (default) up to 8GB
Storage	1 x 2.5" SATA 3.0 SSD (9.5mm)	1 x 2.5" SATA 3.0 SSD (15mm)	1 x 2.5" SATA 2.0 SSD (9.5mm)
Second Storage	1 x mSATA (occupied mini-PCIe socket)	1 x mSATA (occupied mini-PCIe socket)	1 x SD (external accessible)
Video Out	1 x VGA, 1 x HDMI	1 x VGA, 1 x HDMI, 1 x LVDS	1 x VGA, 1 x DP
Audio	1 x Mic-in, 1 x Line-out	1 x Mic-in, 3 x Line-out (selectable)	2 x Mic-in, 2 x Line-out
Ethernet	1 x Intel® 10/100/1000	1 x Intel® 10/100/1000	1 x Intel® 10/100/1000
PoE	N/A	N/A	N/A
I/O Interface			
USB	2 x USB 3.2 (Gen1)	2 x USB 3.2 (Gen1)	1 x USB 3.2 (Gen1), 2 x USB 2.0
COM	5 x RS232, 2 x RS485	5 x RS232, 2 x RS485	2 x RS232 (full), 1 x RS422/485
DIO	5 x Programmable DIO	5 x Programmable DIO	6 x Programmable DIO
CAN Bus	1 x CAN Bus 2.0B	1 x CAN Bus 2.0B	1 x CAN Bus 2.0B
DC Output	12V (2A)	12V (2A)	12V (1A)
SMBus	1	1	N/A
SIM Socket	1	1	2
Expansion			
WWAN	1	1	2
mini-PCIe Socket	- 1 x (USB 2.0, PCIe 2.0/SATA 2.0) - 1 x (USB 2.0) for LTE	- 1 x (USB 2.0, PCIe 2.0/SATA 3.0) - 1 x (USB 2.0) for LTE	- 2 x (USB 2.0, PCIe 2.0) - 1 x (USB 2.0, PCIe 2.0/SATA 2.0) - 1 x (USB 2.0) for LTE
M.2 Socket	N/A	N/A	N/A
GNSS	VIOB-GPS-02 module (u-blox NEO-M8N)	VIOB-GPS-02 module (u-blox NEO-M8N)	VIOB-GPS-02 module (u-blox NEO-M8N)
Power			
Power Input	DC 9V to 36V	DC 9V to 36V	DC 9V to 36V
Back Up Battery	N/A	N/A	N/A
Environment			
Ingress Protection	N/A	N/A	N/A
Certification	CE, FCC Class A, UKCA, E13	CE, FCC Class A, UKCA, E13	CE, FCC Class B, UKCA, E13
Operating Temperature	-40°C to 70°C	-40°C to 70°C	-30°C to 70°C
TPM	TPM 2.0	TPM 2.0	N/A
Others			
OS	Win 10, Linux (Kernel 4.x)	Win 10, Linux (Kernel 4.x)	WES 7, Win 7/8/10 Linux (Kernel 4.x)
Dimensions (mm)	185.0 x 120.0 x 45.0	185.0 x 120.0 x 50.0	180.0 x 180.0 x 50.0



Vehicle Telematics Computer

Model			
	VTC 1021-BK	VTC 1021-C2K	VTC 1030
System			
CPU	Intel Atom® x5-E3940, 4-core, 1.6GHz	Intel Atom® x5-E3940, 4-core, 1.6GHz	Intel Atom® x6211E, 2-core, 1.3GHz
Chipset	N/A	N/A	N/A
Memory	1 x DDR3L 1866 SO-DIMM, 4GB (default) up to 8GB	1 x DDR3L 1866 SO-DIMM, 4GB (default) up to 8GB	1 x DDR4 2666 SO-DIMM, 4GB (default) up to 3200MHz 32GB, in-band ECC support
Storage	1 x 2.5" SATA 3.0 SSD (9.5mm)	1 x 2.5" SATA 3.0 SSD (9.5mm)	1 x 2.5" SATA 3.0 SSD (9.5mm)
Second Storage	1 x mSATA (occupied mini-PCIe socket)	1 x mSATA (occupied mini-PCIe socket)	1 x mSATA (occupied mini-PCIe socket)
I/O Interface			
Video Out	1 x VGA, 1 x HDMI	1 x VGA, 1 x HDMI	1 x VGA, 1 x HDMI
Audio	1 x Mic-in, 1 x Line-out	1 x Mic-in, 1 x Line-out	1 x Mic-in, 1 x Line-out
Ethernet	2 x Intel® 10/100/1000	2 x Intel® 10/100/1000	2 x Intel® 10/100/1000/2500
PoE	N/A	2 x Intel® 10/100/1000 (w/ 802.3af/at). Total 60W	N/A
USB	1 x USB 3.2 (Gen1), 2 x USB 2.0	1 x USB 3.2 (Gen1), 2 x USB 2.0	2 x USB 3.2 (Gen 2)
COM	1 x RS232 (Full), 1 x RS232, 1 x RS422/485	1 x RS232 (Full), 1 x RS232, 1 x RS422/485	2 x RS232 (Full)/422/485
DIO	3 x DI, 3 x DO	3 x DI, 3 x DO	5 x DI, 4 x DO
CAN Bus	1 x CAN Bus 2.0B	1 x CAN Bus 2.0B	1 x CAN Bus 2.0B (w/ isolation)
DC Output	12V (2A)	12V (2A)	12V (2A)
SMBus	1	1	N/A
SIM Socket	2	2	2 (eSIM BOM optional)
WWAN	1	1	1
Expansion			
mini-PCIe Socket	- 1 x (USB 2.0, PCIe 2.0/SATA 3.0) - 1 x (USB 2.0, PCIe 2.0) - 1 x (USB 2.0) for LTE	- 1 x (USB 2.0, PCIe 2.0/SATA 3.0) - 1 x (USB 2.0, PCIe 2.0) - 1 x (USB 2.0) for LTE	- 1 x (USB 2.0, PCIe 3.0/SATA 3.0)
M.2 Socket	N/A	N/A	- 1 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen 2)) for LTE/5G - 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0 x2). BOM optional to 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0, PCIe 3.0)
GNSS	Onboard u-blox NEO-M8N	Onboard u-blox NEO-M8N	VIOB-GPS-06 module (u-blox NEO-M9N)
Power Environment			
Power Input	DC 9V to 36V	DC 9V to 36V	DC 9V to 36V
Back Up Battery	Optional	N/A	N/A
Ingress Protection	N/A	N/A	N/A
Certification	CE, FCC Class A, UKCA, E13	CE, FCC Class A, UKCA, E13	CE, FCC Class A, UKCA, E13
Operating Temperature	-40°C to 70°C	-40°C to 70°C	-40°C to 70°C
TPM	TPM 2.0	TPM 2.0	TPM 2.0
Others			
OS	Win 10, Linux (Kernel 4.x)	Win 10, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)
Dimensions (mm)	180.0 x 180.0 x 50.0	180.0 x 180.0 x 50.0	185.0 x 120.0 x 45.0



Model				
	VTC 1031	VTC 1031-C2	VTC 1040-C2	VTC 6210-BK
System				
CPU	Intel Atom® x6413E, 4-core, 1.5GHz	Intel Atom® x6413E, 4-core, 1.5GHz	Intel Atom® x7211RE, 2-core, 1.0GHz	Intel Atom® E3845, 4-core, 1.91GHz
Chipset	N/A	N/A	N/A	N/A
Memory	1 x DDR4 2666 SO-DIMM, 4GB (default) up to 3200MHz 32GB, in-band ECC support	1 x DDR4 2666 SO-DIMM, 4GB (default) up to 3200MHz 32GB, in-band ECC support	1 x DDR4 3200 SO-DIMM, 4GB (default) up to 16GB, in-band ECC support	1 x DDR3L 1333 SO-DIMM, 4GB (default) up to 8GB
Storage	1 x 2.5" SATA 3.0 SSD (9.5mm)	1 x 2.5" SATA 3.0 SSD (9.5mm)	1 x 2.5" SATA 3.0 SSD (9.5mm)	1 x 2.5" SATA 2.0 SSD (removable, 9.5mm)*
Second Storage	1 x M.2 2280 Key M SSD (SATA 3.0)	1 x M.2 2280 Key M SSD (SATA 3.0)	1 x mSATA (occupied mini-PCIe socket)	1 x CFast (external accessible)
I/O Interface				
Video Out	1 x VGA, 1 x HDMI	1 x VGA, 1 x HDMI	1 x VGA, 1 x HDMI	1 x VGA, 1 x DP
Audio	1 x Mic-in, 1 x Line-out	1 x Mic-in, 1 x Line-out	1 x Mic-in, 1 x Line-out	2 x Mic-in, 2 x Line-out
Ethernet	1 x Intel® 10/100/1000/2500 1 x 10/100/1000	1 x Intel® 10/100/1000/2500 1 x 10/100/1000	3 x Intel® 10/100/1000 (exclusion with PoE)	2 x Intel® 10/100/1000
PoE	N/A	2 x Independent Intel® 10/100/1000 (w/ 802.3af/at). Total 60W	3 x Independent Intel® 2.5GbE (w/ 802.3af/at). Total 30W	N/A
USB	1 x USB 3.2 (Gen 2), 3 x USB 2.0	1 x USB 3.2 (Gen 2), 3 x USB 2.0	1 x USB 3.2 (Gen 2), 1 x USB 2.0	1 x USB 3.2 (Gen1), 2 x USB 2.0
COM	1 x RS232 (Full)/422/485, 1 x RS232, 2 x RS485	1 x RS232 (Full)/422/485, 1 x RS232, 2 x RS485	2 x RS232 (Full)/422/485, 1 x RS232	2 x RS232 (Full), 1 x RS422/485
DIO	5 x DI, 4 x DO	5 x DI, 4 x DO	5 x DI, 4 x DO	8 x Programmable PC GPIO, 2 x MCU-DI, 2 x MCU-DO
CAN Bus	1 x CAN Bus 2.0B (w/ isolation)	1 x CAN Bus 2.0B (w/ isolation)	1 x CAN FD, 1 x CAN Bus 2.0B (w/ isolation)	1 x CAN Bus 2.0B
DC Output	12V (2A)	12V (2A)	N/A	12V (2A)
SMBus	N/A	N/A	N/A	1
SIM Socket	2 (eSIM BOM optional)	2 (eSIM BOM optional)	2 (eSIM BOM optional)	3
WWAN	1	1	2	2
Expansion				
mini-PCIe Socket	- 1 x (USB 2.0, PCIe 3.0). BOM optional to 1 x M.2 3042 Key B socket (USB 2.0, USB 3.2 Gen 2) for LTE/5G	- 1 x (USB 2.0, PCIe 3.0). BOM optional to 1 x M.2 3042 Key B socket (USB 2.0, USB 3.2 Gen 2) for LTE/5G NR	- 1 x (USB 2.0, PCIe 3.0/SATA 2.0)	- 2 x (USB 2.0, PCIe 2.0) - 2 x (USB 2.0) for LTE
M.2 Socket	- 1 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen 2)) for LTE/5G - 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0 x2). BOM optional to 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0, PCIe 3.0)	- 1 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen 2)) for LTE/5G - 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0 x2). BOM optional to 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0, PCIe 3.0)	- 1 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen 2)) for LTE/5G - 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0 x1)	N/A
GNSS	VIOB-GPS-06 module (u-blox NEO-M9N)	VIOB-GPS-06 module (u-blox NEO-M9N)	Onboard u-blox NEO-M9N	VIOB-GPS-02 module (u-blox NEO-M8N)
Power Environment				
Power Input	DC 9V to 36V	DC 9V to 36V	DC 9V to 36V	DC 9V to 36V
Back Up Battery	N/A	N/A	N/A	N/A
Ingress Protection	N/A	N/A	N/A	N/A
Certification	CE, FCC Class A, UKCA, E13	CE, FCC Class A, UKCA, E13	CE, FCC Class A, UKCA, E13	CE, FCC Class B, E13
Operating Temperature	-40°C to 70°C	-40°C to 70°C	-40°C to 70°C	-30°C to 70°C
TPM	TPM 2.0	TPM 2.0	TPM 2.0	N/A
Others				
OS	Win 10/11, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)	WES 7, Win 7/8/ 10 Linux (Kernel 4.x)
Dimensions (mm)	180.0 x 180.0 x 50.0	180.0 x 180.0 x 50.0	185.0 x 120.0 x 45.0	260.0 x 176.0 x 50.0



Vehicle Telematics Computer

Model				 Coming soon
	VTC 6210-VR4	VTC 6220-BK	VTC 6221	VTC 6231
System				
CPU	Intel Atom® E3845, 4-core, 1.91GHz	Intel Atom® x7-E3950, 4-core, 1.6GHz	Intel Atom® x7-E3950, 4-core, 1.6GHz	Intel Atom® x7433RE, 4-core, 1.5GHz
Chipset	N/A	N/A	N/A	N/A
Memory	1 x DDR3L 1333 SO-DIMM, 4GB (default) up to 8GB	1 x DDR3L 1866 SO-DIMM, 4GB (default) up to 8GB	1 x DDR3L 1866 SO-DIMM, 4GB (default) up to 8GB	1 x DDR5 4800 SO-DIMM, 8GB (default) up to 16GB, in-band ECC support
Storage	1 x 2.5" SATA 2.0 SSD (removable, 9.5mm)	2 x 2.5" SATA 3.0 SSD (removable, 9.5mm)	1 x 2.5" SATA 3.0 SSD (removable, 9.5mm)	1 x 2.5" SATA 3.0 SSD (removable, 9.5mm)
Second Storage	1 x CFast (external accessible)	N/A	1 x CFast (external accessible), 1 x mSATA (occupied CFast, BOM optional)	1 x mSATA (occupied mini-PCIe socket)
I/O Interface				
Video Out	VGA, DP, 4 x (Video-in + Audio-in)	1 x VGA, 1 x HDMI, 1 x LVDS (optional), 1 x ultraONE+ (optional)	2 x VGA, 1 x HDMI	1 x VGA, 1 x HDMI, 1 x DP
Audio	2 x Mic-in, 2 x Line-out	2 x Mic-in, 2 x Line-out	1 x Mic-in, 2 x Line-out	1 x Mic-in, 1 x Line-in, 1 x Line-out
Ethernet	2 x Intel® 10/100/1000	3 x Intel® 10/100/1000 (2 x LAN exclusion with PoE)	2 x Intel® 10/100/1000, (3 BOM optional)	2 x Intel® 10/100/1000/2500
PoE	N/A	2 x independent Intel® 10/100/1000 (w/ 802.3af/at). Total 30W (BOM optional)	N/A	N/A
USB	1 x USB 3.2 (Gen1), 2 x USB 2.0	2 x USB 3.2 (Gen1), 1 x USB 2.0	3 x USB 2.0, 1 x USB 3.2 (Gen1)	2 x USB 2.0, 2 x USB 3.2 (Gen2)
COM	1 x RS232 (Full), 1 x RS422/485	2 x RS232 (Full), 1 x RS422/485	1 x RS232 (Full), 1 x RS232, 1 x RS485	2 x RS232(Full)/422/485, 1 x RS232 (Full)
DIO	8 x Programmable PC GPIO, 2 x MCU-DI, 2 x MCU-DO*	4 x DI, 4 x DO	4 x DI, 4 x DO	4 x DI, 4 x DO
CAN Bus	1 x CAN Bus 2.0B	1 x CAN Bus 2.0B (w/ isolation)	1 x CAN Bus 2.0B (w/ isolation)	1 x CAN FD (w/ isolation)
DC Output	12V (2A)	12V (2A)	12V (2A)	12V (2A)
SMBus	1	1	N/A	N/A
SIM Socket	3	4	6 (BOM option up to 8, eSIM BOM optional)	8 (eSIM BOM optional)
WWAN	2	2	3 (BOM optional up to 4)	3 (BOM optional up to 4)
Expansion				
mini-PCIe Socket	- 2 x (USB 2.0, PCIe 2.0) - 2 x (USB 2.0) for LTE	- 2 x (USB 2.0, PCIe 2.0) - 1 x (USB 2.0) for LTE. BOM Option to 1 x M.2 3042 Key B (USB 2.0, USB 3.2 (Gen1)) for LTE/5G	- 1 x (USB 2.0, PCIe 2.0) - 1 x (USB 2.0, PCIe 2.0). BOM optional to 1 x mini-PCIe (USB 2.0) for LTE - 1 x (USB 2.0) for LTE	- 1 x (USB 2.0, SATA 3.0/PCIe 3.0) default for mSATA, BIOS select (USB 2.0) for LTE, BOM optional (USB 2.0, PCIe 3.0) - 1 x (USB 2.0, PCIe 3.0), BOM optional to 1 x M.2 3052 Key B (USB 2.0, USB 3.2 Gen 2) for LTE/5G
M.2 Socket	N/A	- 1 x M.2 3042 Key B (USB 2.0, USB 3.2 (Gen1)) for LTE/5G	- 1 x M.2 3042/3052 Key B (USB 2.0, USB 3.2 (Gen1)) for LTE/5G - 1 x M.2 3042 Key B (USB 2.0, USB 3.2 (Gen1)) for LTE/5G	- 2 x M.2 3042/3052 Key B (USB 2.0, USB 3.2 (Gen2)) for LTE/5G - 1 x M.2 2230 Key E (PCIe 3.0 x 1, USB 2.0), BOM optional mPCIe (PCIe 3.0 x 1, USB 2.0) for Halo module
GNSS	VIOB-GPS-02 module (u-blox NEO-M8N)	VIOB-GPS-02 module (u-blox NEO-M8N)	VIOB-GPS-02 module (u-blox NEO-M8N)	VIOB-GPS-06 module (u-blox NEO-M9N)
Power Environment				
Power Input	DC 9V to 36V	DC 9V to 36V	DC 9V to 48V	DC 9V to 36V
Back Up Battery	N/A	Optional	N/A	N/A
Ingress Protection	N/A	N/A	N/A	N/A
Certification	CE, FCC Class B, UKCA, E13	CE, FCC Class A, UKCA, E13	CE, FCC Class A, UKCA, E13	CE, FCC Class A, UKCA, E13
Operating Temperature	-30°C to 70°C	-40°C to 70°C	-40°C to 70°C	-40°C to 70°C
Others				
TPM	N/A	TPM 2.0	TPM 2.0, optional	TPM 2.0
OS	WES 7, Win 7/8/10 Linux (Kernel 4.x)	Win 10, Linux (Kernel 4.x)	Win 10, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)
Dimensions (mm)	260.0 x 176.0 x 50.0	260.0 x 196.0 x 50.0	260.0 x 196.0 x 50.0	260.0 x 196.0 x 50.0



Model			
	VTC 6231-IP	VTC 6232-C4S	VTC 6232-C4S-BAT
System			
CPU	Intel Atom® x7433RE, 4-core, 1.5GHz	Intel Atom® x7433RE, 4-core, 1.5GHz	Intel Atom® x7433RE, 4-core, 1.5GHz
Chipset	N/A	N/A	N/A
Memory	1 x DDR5 4800 SO-DIMM, 8GB (default) up to 16GB, in-band ECC support	1 x DDR5 4800 SO-DIMM, 8GB (default) up to 16GB, in-band ECC support	1 x DDR5 4800 SO-DIMM, 8GB (default) up to 16GB, in-band ECC support
Storage	1 x 2.5" SATA 3.0 SSD (removable, 9.5mm)	eMMC 5.1, 64GB	eMMC 5.1, 64GB
Second Storage	1 x mSATA (occupied mini-PCIe socket)	2 x 2.5" SATA 3.0 SSD (removable, 15mm)	1 x 2.5" SATA 3.0 SSD (removable, 15mm), 1 x M.2 2242 Key B (SATA)
I/O Interface			
Video Out	1 x VGA, 1 x HDMI	1 x VGA, 1 x HDMI, 1 x DP	1 x VGA, 1 x HDMI, 1 x DP
Audio	1 x Mic-in, 1 x Line-in, 1 x Line-out	1 x Mic-in, 1 x Line-in, 1 x Line-out	1 x Mic-in, 1 x Line-in, 1 x Line-out
Ethernet	2 x Intel® 10/100/1000/2500	1 x Intel® 10/100/1000/2500	1 x Intel® 10/100/1000/2500
PoE	N/A	4 x Intel® 2.5GbE (w/ 802.3af/at/bt). Total 90W	4 x Intel® 2.5GbE (w/ 802.3af/at/bt). Total 90W
USB	2 x USB 2.0, 2 x USB 3.2 (Gen2)	2 x USB 2.0, 2 x USB 3.2 (Gen2)	2 x USB 2.0, 2 x USB 3.2 (Gen2)
COM	2 x RS232(Full)/422/485, 1 x RS232 (Full)	2 x RS232(Full)/422/485, 1 x RS232, 1 x RS422/485	2 x RS232(Full)/422/485, 1 x RS232, 1 x RS422/485
DIO	4 x DI, 4 x DO	4 x DI, 4 x DO	4 x DI, 4 x DO
CAN Bus	1 x CAN FD (w/ isolation)	1 x CAN FD (w/ isolation)	1 x CAN FD (w/ isolation)
DC Output	12V (2A)	12V (2A)	12V (2A)
SMBus	N/A	N/A	N/A
SIM Socket	8 (eSIM BOM optional)	4 (eSIM BOM optional)	4 (eSIM BOM optional)
WWAN	3 (BOM optional up to 4)	2	2
Expansion			
mini-PCIe Socket	- 1 x (USB 2.0, SATA 3.0/PCIe 3.0) default for mSATA, BIOS select (USB 2.0) for LTE, BOM optional (USB 2.0, PCIe 3.0) - 1 x (USB 2.0, PCIe 3.0), BOM optional to 1 x M.2 3052 Key B (USB 2.0, USB 3.2 Gen 2) for LTE/5G	- 1 x (USB 2.0, PCIe 3.0), BOM optional to 1 x M.2 3052 Key B (USB 2.0, USB 3.2 Gen 2) for LTE/5G	- 1 x (USB 2.0, PCIe 3.0), BOM optional to 1 x M.2 3052 Key B (USB 2.0, USB 3.2 Gen 2) for LTE/5G
M.2 Socket	- 2 x M.2 3042/3052 Key B (USB 2.0, USB 3.2 (Gen2)) for LTE/5G - 1 x M.2 2230 Key E (PCIe 3.0 x 1, USB 2.0), BOM optional mPCIe (PCIe 3.0 x 1, USB 2.0) for Halo module	- 1 x M.2 3042/3052 Key B (USB 2.0, USB 3.2 (Gen2)) for LTE/5G - 1 x M.2 2230 Key E (PCIe 3.0 x 1, USB 2.0), BOM optional mPCIe (PCIe 3.0 x 1, USB 2.0) for Halo module	- 1 x M.2 3042/3052 Key B (USB 2.0, USB 3.2 (Gen2)) for LTE/5G - 1 x M.2 2230 Key E (PCIe 3.0 x 1, USB 2.0), BOM optional mPCIe (PCIe 3.0 x 1, USB 2.0) for Halo module
GNSS	VIOB-GPS-06 module (u-blox NEO-M9N)	VIOB-GPS-07 module (u-blox NEO-M9N)	VIOB-GPS-07 module (u-blox NEO-M9N)
Power Environment			
Power Input	DC 9V to 36V	DC 9V to 48V	DC 9V to 48V
Back Up Battery	N/A	N/A	YES
Ingress Protection	N/A	N/A	N/A
Certification	CE, FCC Class A, UKCA, E13	CE, FCC Class A, UKCA, E13	CE, FCC Class A, UKCA, E13
Operating Temperature	-40°C to 70°C	-40°C to 70°C	-40°C to 70°C
Others			
TPM	TPM 2.0	TPM 2.0	TPM 2.0
OS	Win 10/11, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)
Dimensions (mm)	260.0 x 196.0 x 70.0	260.0 x 196.0 x 66.5	260.0 x 196.0 x 66.5

Vehicle Telematics Computer

Model	Coming Soon		Coming Soon	
	VTC 6232-C4SIP	VTC 6232-C4SIP-BAT	VTC 6222-C4S	VTC 7250-7C8
CPU	Intel Atom® x7433RE, 4-core, 1.5GHz	Intel Atom® x7433RE, 4-core, 1.5GHz	Intel Atom® x7-E3950, 4-core, 1.6GHz	Intel® Core™ i7-8700T, 6-core, 2.4GHz
Chipset	N/A	N/A	N/A	Intel® Q370
Memory	1 x DDR5 4800 SO-DIMM, 8GB (default) up to 16GB, in-band ECC support	1 x DDR5 4800 SO-DIMM, 8GB (default) up to 16GB, in-band ECC support	1 x DDR3L 1866 SO-DIMM, 4GB (default) up to 8GB	2 x DDR4 2666 SO-DIMM, 4GB+4GB (default) up to 32GB+32GB
Storage	eMMC 5.1, 64GB	eMMC 5.1, 64GB	2 x 2.5" SATA 3.0 SSD (removable, 15mm)	2 x 2.5" SATA 3.0 SSD (removable, 15mm)
Second Storage	2 x 2.5" SATA 3.0 SSD (removable, 15mm)	1 x 2.5" SATA 3.0 SSD (removable, 15mm), 1 x M.2 2242 Key B (SATA)	1 x SD (external accessible), 1 x Internal USB DOM	2 x mSATA 3.0 (BIOS selection)
Video Out	1 x VGA, 1 x HDMI (optional)	1 x VGA, 1 x HDMI (optional)	1 x VGA, 2 x HDMI	1 x VGA, 1 x HDMI, 1 x ultraONE+
Audio	1 x Mic-in, 1 x Line-in, 1 x Line-out	1 x Mic-in, 1 x Line-in, 1 x Line-out	1 x Mic-in, 2 x Line-out	1 x Mic-in, 1 x Line-out
Ethernet	1 x Intel® 10/100/1000/2500	1 x Intel® 10/100/1000/2500	1 x Intel® 10/100/1000	1 x Intel® 10/100/1000
PoE	4 x Intel® 2.5GbE (w/ 802.3af/at/bt). Total 90W	4 x Intel® 2.5GbE (w/ 802.3af/at/bt). Total 90W	4 x Intel® 10/100/1000 (w/ 802.3af/at). Total 60W	8 x independent Intel® 10/100/1000 (w/ 802.3af/at). Total 60W
USB	2 x USB 2.0, 1 x USB 3.2 (Gen2)	2 x USB 2.0, 1 x USB 3.2 (Gen2)	1 x USB 3.2 (Gen1), 2 x USB 2.0	6 x USB 3.2 (Gen2)
COM	2 x RS232(Full)/422/485, 1 x RS232, 1 x RS422/485	2 x RS232(Full)/422/485, 1 x RS232, 1 x RS422/485	1 x RS232 (Full), 1 x RS232, 1 x RS422/485	2 x RS232 (Full), 1 x RS232 (Full)/422/485
DIO	4 x DI, 4 x DO	4 x DI, 4 x DO	4 x DI, 4 x DO (w/ isolation)	4 x DI, 4 x DO
CAN Bus	1 x CAN FD (w/ isolation)	1 x CAN FD (w/ isolation)	1 x CAN Bus 2.0B (w/ isolation)	1 x CAN Bus 2.0B (w/ isolation)
DC Output	12V (2A)	12V (2A)	12V (2A)	12V (2A)
SMBus	N/A	N/A	N/A	N/A
SIM Socket	4 (eSIM BOM optional)	4 (eSIM BOM optional)	2 (eSIM BOM optional)	3 (eSIM BOM optional)
WWAN	2	2	1	2
mini-PCIe Socket	- 1x(USB 2.0, PCIe 3.0), BOM optional to 1xM.2 3052 Key B (USB 2.0, USB 3.2 Gen2) for LTE/5G	- 1x(USB 2.0, PCIe 3.0), BOM optional to 1xM.2 3052 Key B (USB 2.0, USB 3.2 Gen2) for LTE/5G	- 2x(USB 2.0, PCIe 2.0) - 1x(USB 2.0) for LTE, BOM optional to 1xM.2 3042 Key B (USB 2.0, USB 3.2 (Gen1)) for LTE/5G	- 2x(USB 2.0, PCIe 3.0/SATA 3.0) - 1x(USB 2.0) for LTE, BOM optional to 1xM.2 3042 Key B (USB 2.0, USB 3.2 (Gen1)) for LTE/5G
M.2 Socket	- 1xM.2 3042/3052 Key B (USB 2.0, USB 3.2(Gen2)) for LTE/5G - 1xM.2 2230 Key E (PCIe 3.0 x 1, USB 2.0), BOM optional mPCIe (PCIe 3.0 x 1, USB 2.0) for Hailo module	- 1xM.2 3042/3052 Key B (USB 2.0, USB 3.2(Gen2)) for LTE/5G - 1xM.2 2230 Key E (PCIe 3.0 x 1, USB 2.0), BOM optional mPCIe (PCIe 3.0 x 1, USB 2.0) for Hailo module	N/A	- 1xM.2 3042 Key B (USB 2.0, USB 3.2 (Gen1)) for LTE/5G
GNSS	VIOB-GPS-07 module (u-blox NEO-M9N)	VIOB-GPS-07 module (u-blox NEO-M9N)	u-blox NEO-M8N on board	VIOB-GPS-02 module (u-blox NEO-M8N)
Power Input	DC 9V to 48V	DC 9V to 48V	DC 9V to 48V	DC 9V to 36V
Back Up Battery	N/A	YES	N/A	N/A
Ingress Protection	IP67	IP67	N/A	N/A
Certification	CE, FCC Class A, UKCA, E13	CE, FCC Class A, UKCA, E13	CE, FCC Class A, UKCA, E13	CE, FCC Class A, UKCA, E13
Operating Temperature	-40°C to 70°C	-40°C to 70°C	-40°C to 70°C	-30°C to 60°C
TPM	TPM 2.0	TPM 2.0	TPM 2.0, optional	TPM 2.0
OS	Win 10/11, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)	Win 10, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)
Dimensions (mm)	260.0 x 196.0 x 86.5	260.0 x 196.0 x 86.5	260.0 x 196.0 x 66.5	260.0 x 256.0 x 90.1



Model	Coming Soon		Coming Soon	
	VTC 7251	VTC 7251-7C4	VTC 7252-7C4IP	
CPU	Intel® Core™ i7-8700T, 6-core, 2.4GHz	Intel® Core™ i7-8700T, 6-core, 2.4GHz	Intel® Core™ i7-9700TE, 8-core, 1.8GHz	
Chipset	Intel® Q370	Intel® Q370	Intel® C246	
Memory	2 x DDR4 2666 SO-DIMM, 4GB+4GB (default) up to 32GB+32GB	2 x DDR4 2666 SO-DIMM, 4GB+4GB (default) up to 32GB+32GB	2 x DDR4 2666 SO-DIMM, 4GB+4GB (default) up to 32GB+32GB	
Storage	2 x 2.5" SATA 3.0 SSD (removable, 15mm)	2 x 2.5" SATA 3.0 SSD (removable, 15mm)	2 x 2.5" SATA 3.0 SSD (removable, 15mm)	
Second Storage	2 x mSATA 3.0 (BIOS selection)	2 x mSATA 3.0 (BIOS selection)	2 x mSATA 3.0 (BIOS selection), 1 x CFast (external accessible)	
Video Out	1 x VGA, 1 x HDMI	1 x VGA, 1 x HDMI	1 x VGA, 1 x HDMI (optional)	
Audio	1 x Mic-in, 2 x Line-out	1 x Mic-in, 2 x Line-out	1 x Mic-in, 2 x Line-out	
Ethernet	2 x Intel® 10/100/1000	1 x Intel® 10/100/1000	2 x Intel® 10/100/1000	
PoE	N/A	4 x independent Intel® 10/100/1000 (w/ 802.3af/at). Total 60W	4 x independent Intel® 10/100/1000 (w/ 802.3af/at). Total 60W	
USB	6 x USB 3.2 (Gen2)	6 x USB 3.2 (Gen2)	2 x USB 3.2 (Gen2), 2 x USB 2.0	
COM	2 x RS232 (Full), 1 x RS232 (Full)/422/485	2 x RS232 (Full), 1 x RS232 (Full)/422/485	2 x RS232 (Full), 1 x RS232 (Full)/422/485	
DIO	4 x DI, 4 x DO	4 x DI, 4 x DO	3 x DI, 3 x DO	
CAN Bus	1 x CAN Bus 2.0B (w/ isolation)	1 x CAN Bus 2.0B (w/ isolation)	2 x CAN Bus 2.0B (w/ isolation)	
DC Output	12V (2A)	12V (2A)	12V (2A)	
SMBus	N/A	N/A	N/A	
SIM Socket	6 (BOM option up to 8, eSIM BOM optional)	6 (BOM option up to 8, eSIM BOM optional)	2 (eSIM BOM optional)	
WWAN	3 (BOM optional up to 4)	3	1	
mini-PCIe Socket	- 2x(USB 2.0, PCIe 3.0/SATA 3.0) - 2x(USB 2.0) for LTE, BOM optional to 2xM.2 3042 Key B (USB 2.0, USB 3.2 (Gen1)) for LTE/5G	- 2x(USB 2.0, PCIe 3.0/SATA 3.0) - 2x(USB 2.0) for LTE, BOM optional to M.2 3042 Key B (USB 2.0, USB 3.2 (Gen1)) for LTE/5G	- 2x(USB 2.0, PCIe 3.0/SATA 3.0)	
M.2 Socket	- 1xM.2 3042/3052 Key B (USB 2.0, USB 3.2 (Gen1)) for LTE/5G	- 1xM.2 3042/3052 Key B (USB 2.0, USB 3.2 (Gen1)) for LTE/5G	- 1xM.2 3042/3052 Key B (USB 2.0, USB 3.2 (Gen1)) for LTE/5G - 1xM.2 2230 Key E (USB 2.0, 2xPCIe 3.0), BOM optional to 1xmini-PCIe(USB 2.0, PCIe 3.0).	
GNSS	VIOB-GPS-02 module (u-blox NEO-M8N)	VIOB-GPS-02 module (u-blox NEO-M8N)	VIOB-GPS-02 module (u-blox NEO-M8N)	
Power Input	DC 9V to 36V	DC 9V to 36V	DC 9V to 36V	
Back Up Battery	N/A	N/A	N/A	
Ingress Protection	N/A	N/A	IP65	
Certification	CE, FCC Class A, UKCA, E13	CE, FCC Class A, UKCA, E13	CE, FCC Class A, UKCA, E13	
Operating Temperature	-30°C to 70°C	-30°C to 60°C	-30°C to 60°C	
TPM	TPM 2.0	TPM 2.0	TPM 2.0	
OS	Win 10/11, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)	
Dimensions (mm)	260.0 x 256.0 x 83.5	260.0 x 256.0 x 83.5	260.0 x 256.0 x 66.5	

Vehicle Telematics Computer

Model			
	VTC 7260-5	VTC 7260-5C4	VTC 7260-7
System			
CPU	Intel® Core™ i5-1145GRE, 4-core, 1.5GHz	Intel® Core™ i5-1145GRE, 4-core, 1.5GHz	Intel® Core™ i7-1185GRE, 4-core, 1.8GHz
Chipset	N/A	N/A	N/A
Memory	2 x DDR4 3200 SO-DIMM, 4GB+4GB (default) up to 32GB+32GB, in-band ECC support	2 x DDR4 3200 SO-DIMM, 4GB+4GB (default) up to 32GB+32GB, in-band ECC support	2 x DDR4 3200 SO-DIMM, 4GB+4GB (default) up to 32GB+32GB, in-band ECC support
Storage	1 x 2.5" SATA 3.0 SSD (15mm)	1 x 2.5" SATA 3.0 SSD (15mm)	1 x 2.5" SATA 3.0 SSD (15mm)
Second Storage	1 x mSATA 3.0, 1 x M.2 2280 Key M NVMe (PCIe4.0 x4)	1 x mSATA 3.0, 1 x M.2 2280 Key M NVMe (PCIe4.0 x4)	1 x mSATA 3.0, 1 x M.2 2280 Key M NVMe (PCIe4.0 x4)
Video Out	1 x VGA, 1 x HDMI, 1 x DP	1 x VGA, 1 x HDMI, 1 x DP	1 x VGA, 1 x HDMI, 1 x DP
Audio	1 x Mic-in, 1 x Line-out	1 x Mic-in, 1 x Line-out	1 x Mic-in, 1 x Line-out
Ethernet	1 x Intel® 10/100/1000 (WoL, PXE, iAMT support), 2 x independent Intel® 2.5GbE	1 x Intel® 10/100/1000 (WoL, PXE, iAMT support)	1 x Intel® 10/100/1000 (WoL, PXE, iAMT support), 2 x independent Intel® 2.5GbE
I/O Interface			
PoE	N/A	4 x independent Intel® 2.5GbE (w/ 802.3af/at). Total 60W	N/A
USB	3 x USB 3.2 (Gen1), 1 x USB 2.0	3 x USB 3.2 (Gen1), 1 x USB 2.0	3 x USB 3.2 (Gen1), 1 x USB 2.0
COM	1 x RS232 (Full), 2 x RS232 (Full)/422/485	2 x RS232 (Full)/422/485	1 x RS232 (Full), 2 x RS232 (Full)/422/485
DIO	4 x DI, 4 x DO	4 x DI, 4 x DO	4 x DI, 4 x DO
CAN Bus	1 x CAN Bus 2.0B (w/ isolation)	1 x CAN Bus 2.0B (w/ isolation)	1 x CAN Bus 2.0B (w/ isolation)
DC Output	N/A	N/A	N/A
SMBus	N/A	N/A	N/A
SIM Socket	4	4	4
WWAN	2	2	2
Expansion			
mini-PCIe Socket	- 1 x (PCIe 3.0/USB3.2, USB2.0) for LTE/5G	- 1 x (PCIe 3.0/USB3.2, USB 2.0) for LTE/5G	- 1 x (PCIe 3.0/USB3.2, USB 2.0) for LTE/5G
M.2 Socket	- 1 x M.2 3042/3052 Key B (USB 3.2 (Gen2)) for LTE/5G - 1 x M.2 3042 Key E (PCIe3.0 x2, USB2.0) for WiFi/Hailo AI card	- 1 x M.2 3042/3052 Key B (USB 3.2 (Gen2)) for LTE/5G - 1 x M.2 3042 Key E (PCIe3.0 x2, USB2.0) for WiFi/Hailo AI card	- 1 x M.2 3042/3052 Key B (USB 3.2 (Gen2)) for LTE/5G - 1 x M.2 3042 Key E (PCIe3.0 x2, USB2.0) for WiFi/Hailo AI card
GNSS	VIOB-GPS-06 module (u-blox NEO-M9N)	VIOB-GPS-06 module (u-blox NEO-M9N)	VIOB-GPS-06 module (u-blox NEO-M9N)
Power			
Power Input	DC 9V to 36V	DC 9V to 36V	DC 9V to 36V
Back Up Battery	N/A	N/A	N/A
Ingress Protection	N/A	N/A	N/A
Environment			
Certification	CE, FCC Class A, UKCA, E13	CE, FCC Class A, UKCA, E13	CE, FCC Class A, UKCA, E13
Operating Temperature	-30°C to 65/70°C (15W/12W TDP)	-30°C to 60°C (15W TDP & PoE)	-30°C to 65/70°C (15W/12W TDP)
TPM	TPM 2.0	TPM 2.0	TPM 2.0
Others			
OS	Win 10/11, Linux (Kernel 5.x)	Win 10/11, Linux (Kernel 5.x)	Win 10/11, Linux (Kernel 5.x)
Dimensions (mm)	210.0 x 173.0 x 75.0	210.0 x 173.0 x 75.0	210.0 x 173.0 x 75.0



Model			
	VTC 7260-7C4	VTC 7270	VTC 7270-C4/C8
System			
CPU	Intel® Core™ i7-1185GRE, 4-core, 1.8GHz	12/13th Gen Intel® Core™ i	12/13th Gen Intel® Core™ i
Chipset	N/A	R680E	R680E
Memory	2 x DDR4 3200 SO-DIMM, 4GB+4GB (default) up to 32GB+32GB, in-band ECC support	2 x DDR5 4800 SO-DIMM, up to 32GB+32GB, ECC support	2 x DDR5 4800 SO-DIMM, up to 32GB+32GB, ECC support
Storage	1 x 2.5" SATA 3.0 SSD (15mm)	2 x 2.5" SATA 3.0 SSD (removable, 15mm)	2 x 2.5" SATA 3.0 SSD (removable, 15mm)
Second Storage	1 x mSATA 3.0, 1 x M.2 2280 Key M NVMe (PCIe4.0 x4)	1 x M.2 2280 Key M NVMe (PCIe4.0 x4)	1 x M.2 2280 Key M NVMe (PCIe4.0 x4)
Video Out	1 x VGA, 1 x HDMI, 1 x DP	1 x VGA, 1 x HDMI, 1 x DP	1 x VGA, 1 x HDMI, 1 x DP
Audio	1 x Mic-in, 1 x Line-out	1 x Mic-in, 1 x Line-in, 1 x Line-out	1 x Mic-in, 1 x Line-in, 1 x Line-out
Ethernet	1 x Intel® 10/100/1000 (WoL, PXE, iAMT support)	1 x Intel® 10/100/1000 (WoL, PXE, iAMT support), 2 x independent Intel® 2.5GbE	1 x Intel® 10/100/1000 (WoL, PXE, iAMT support)
I/O Interface			
PoE	4 x independent Intel® 2.5GbE (w/ 802.3af/at). Total 60W	N/A	4/8 x independent Intel® 2.5GbE (w/ 802.3af/at, total 60W/120W)
USB	3 x USB 3.2 (Gen1), 1 x USB 2.0	6 x USB 3.2 (Gen2)	6 x USB 3.2 (Gen2)
COM	2 x RS232 (Full)/422/485	2 x RS232 (Full), 2 x RS232 (Full)/422/485	2 x RS232 (Full), 2 x RS232 (Full)/422/485
DIO	4 x DI, 4 x DO	4 x DI, 4 x DO	4 x DI, 4 x DO
CAN Bus	1 x CAN Bus 2.0B (w/ isolation)	2 x CAN FD (w/ isolation)	2 x CAN FD (w/ isolation)
DC Output	N/A	12V (2A)	12V (2A)
SMBus	N/A	N/A	N/A
SIM Socket	4	4	4
WWAN	2	2	2
Expansion			
mini-PCIe Socket	- 1 x (PCIe 3.0/USB3.2, USB 2.0) for LTE/5G	- 1 x (PCIe 3.0, SATA 3.0, USB3.2), default PCIe 3.0 - 1 x (USB 3.2, PCIe 3.0, SATA 3.0), default USB 3.2 for LTE	- 1 x (PCIe 3.0, SATA 3.0, USB3.2), default PCIe 3.0 - 1 x (USB 3.2, PCIe 3.0, SATA 3.0), default USB 3.2 for LTE
M.2 Socket	- 1 x M.2 3042/3052 Key B (USB 3.2 (Gen2)) for LTE/5G - 1 x M.2 3042 Key E (PCIe3.0 x2, USB 2.0) for Wi-Fi/Hailo AI card	- 1 x M.2 3042/3052 Key B (USB 2.0, USB 3.2 (Gen2)) for LTE/5G - 1 x M.2 2230 Key E (PCIe 3.0 x2, USB 2.0) for Wi-Fi/Hailo AI card	- 1 x M.2 3042/3052 Key B (USB 3.2 (Gen2)) for LTE/5G - 1 x M.2 3030 Key E (PCIe 3.0 x2, USB 2.0) for Wi-Fi/Hailo AI card
GNSS	VIOB-GPS-06 module (u-blox NEO-M9N)	VIOB-GPS-06 module (u-blox NEO-M9N)	VIOB-GPS-06 module (u-blox NEO-M9N)
Power			
Power Input	DC 9V to 36V	DC 9V to 36V	DC 9V to 36V
Back Up Battery	N/A	N/A	N/A
Ingress Protection	N/A	N/A	N/A
Environment			
Certification	CE, FCC Class A, UKCA, E13	CE, FCC Class A, UKCA, E13	CE, FCC Class A, UKCA, E13
Operating Temperature	-30°C to 60°C (15W TDP & PoE)	-35°C to 70°C (35W TDP, fanless; 65W CPU, w/ fan)	-35°C to 60°C/65°C (35W CPU, fanless, POW/60W; POE: 65W CPU w/ fan, 120W/60W PoE)
TPM	TPM 2.0	TPM 2.0	TPM 2.0
Others			
OS	Win 10/11, Linux (Kernel 5.x)	Win 10/11, Linux (Kernel 5.x)	Win 10/11, Linux (Kernel 5.x)
Dimensions (mm)	210.0 x 173.0 x 75.0	260.0 x 210.0 x 81.0	260.0 x 210.0 x 81.0



Modular Vehicle Computer System

Model					
	MVS 2620-IP	MVS 5600-3BU	MVS 5600-7BU	MVS 5600-3IPK	MVS 5600-7IPK
System	CPU: Intel Atom® x7-E3950, 4-core, 1.6GHz Chipset: N/A Memory: 1 x DDR3L 1600/1866 SO-DIMM, 4GB (default) up to 8GB Storage: 1 x 2.5" SATA 3.0 SSD/HDD	CPU: Intel® Core™ i3-6100U, 2-core, 2.3GHz Chipset: N/A Memory: 2 x DDR3L 1600/1866 SO-DIMM, 2GB (default) up to 16GB Storage: 1 x 2.5" SATA 3.0 SSD/HDD (removable, 9.5mm)	CPU: Intel® Core™ i7-6600U, 2-core, 2.6GHz Chipset: N/A Memory: 2 x DDR3L 1600/1866 SO-DIMM, 2GB (default) up to 16GB Storage: 1 x 2.5" SATA 3.0 SSD/HDD (removable, 9.5mm)	CPU: Intel® Core™ i3-6100U, 2-core, 2.3GHz Chipset: N/A Memory: 2 x DDR3L 1600/1866 SO-DIMM, 2GB (default) up to 16GB Storage: 1 x 2.5" SATA 3.0 SSD/HDD	CPU: Intel® Core™ i7-6600U, 2-core, 2.6GHz Chipset: N/A Memory: 2 x DDR3L 1600 SO-DIMM, 2GB (default) up to 16GB Storage: 1 x 2.5" SATA 3.0 SSD/HDD
I/O Interface	Second Storage: 1 x CFast (removable) Video Out: 1 x VGA Audio: 1 x Mic-in, 2 x Line-out Ethernet: 2 x Intel® 10/100/1000 PoE: N/A USB: 3 x USB 2.0 COM: 2 x RS232 (Full), 1 x RS232, 2 x RS485 DIO: 3 x DI, 3 x DO (w/ isolation) CAN Bus: 1 x CANBus 2.0B (w/ isolation) DC Output: 12V (2A) SIM Socket: 3 WWAN: 2	Second Storage: 1 x CFast (removable) Video Out: 1 x VGA, 1 x HDMI Audio: 2 x Mic-in, 2 x Line-out Ethernet: 2 x Intel® 10/100/1000 PoE: N/A USB: 4 x USB 3.2 (Gen1) COM: 2 x RS232 (Full), 1 x RS232 (Full)/422/485 DIO: 8 x Programmable DIO MCU: 2 x DI, 2 x DO, 1 x Speed frequency CAN Bus: 1 x CAN Bus 2.0B DC Output: 12V (2A) SIM Socket: 3 WWAN: 2	Second Storage: 1 x CFast (removable) Video Out: 1 x VGA, 1 x HDMI Audio: 2 x Mic-in, 2 x Line-out Ethernet: 2 x Intel® 10/100/1000 PoE: N/A USB: 4 x USB 3.2 (Gen1) COM: 2 x RS232 (Full), 1 x RS232 (Full)/422/485 DIO: 8 x Programmable DIO MCU: 2 x DI, 2 x DO, 1 x Speed frequency CAN Bus: 1 x CAN Bus 2.0B DC Output: 12V (2A) SIM Socket: 3 WWAN: 2	Second Storage: 1 x CFast (removable) Video Out: 1 x VGA Audio: 1 x Mic-in, 2 x Line-out Ethernet: 2 x Intel® 10/100/1000 PoE: N/A USB: 1 x USB 3.2 (Gen1), 2 x USB 2.0 COM: 2 x RS232 (Full), 1 x RS232, 2 x RS485 DIO: 3 x DI, 3 x DO (w/ isolation) CAN Bus: 1 x CAN Bus 2.0B (w/ isolation) DC Output: 12V (2A) SIM Socket: 3 WWAN: 2	Second Storage: 1 x CFast (removable) Video Out: 1 x VGA Audio: 1 x Mic-in, 2 x Line-out Ethernet: 2 x Intel® 10/100/1000 PoE: N/A USB: 1 x USB 3.2 (Gen1), 2 x USB 2.0 COM: 2 x RS232 (Full), 1 x RS232, 2 x RS485 DIO: 3 x DI, 3 x DO (w/ isolation) CAN Bus: 1 x CAN Bus 2.0B (w/ isolation) DC Output: 12V (2A) SIM Socket: 3 WWAN: 2
Expansion	mini-PCIe Socket: - 1 x (USB2.0, PCIe2.0) for LTE - 1 x (USB2.0) for LTE - 1 x (USB2.0, PCIe2.0) - 1 x (USB2.0) M.2 Socket: N/A GNSS: VIOB-GPS-02 module (u-blox NEO-M8N)	mini-PCIe Socket: - 1 x (USB2.0, PCIe2.0) for LTE - 1 x (USB2.0) for LTE - 1 x (USB2.0, PCIe2.0) - 1 x (USB2.0, PCIe2.0) M.2 Socket: N/A GNSS: VIOB-GPS-02 module (u-blox NEO-M8N)	mini-PCIe Socket: - 1 x (USB2.0, PCIe2.0) for LTE - 1 x (USB2.0) for LTE - 1 x (USB2.0, PCIe2.0) - 1 x (USB2.0, PCIe2.0) M.2 Socket: N/A GNSS: VIOB-GPS-02 module (u-blox NEO-M8N)	mini-PCIe Socket: - 1 x (USB2.0, PCIe2.0) for LTE - 1 x (USB2.0) for LTE - 1 x (USB2.0, PCIe2.0) - 1 x (USB2.0) M.2 Socket: N/A GNSS: VIOB-GPS-02 module (u-blox NEO-M8N)	mini-PCIe Socket: - 1 x (USB2.0, PCIe2.0) for LTE - 1 x (USB2.0) for LTE - 1 x (USB2.0, PCIe2.0) - 1 x (USB2.0) M.2 Socket: N/A GNSS: VIOB-GPS-02 module (u-blox NEO-M8N)
Power	Power Input: DC 9V to 36V Back Up Battery: N/A	Power Input: DC 9V to 36V Back Up Battery: Internal (optional)	Power Input: DC 9V to 36V Back Up Battery: Internal (optional)	Power Input: DC 9V to 36V Back Up Battery: N/A	Power Input: DC 9V to 36V Back Up Battery: N/A
Environment	Ingress Protection: IP65 Certification: CE, FCC Class A, UKCA, E13 Operating Temperature: -40°C to 70°C TPM: N/A	Ingress Protection: N/A Certification: CE, FCC Class A, UKCA, E13 Operating Temperature: -30°C to 60°C TPM: TPM 2.0, optional	Ingress Protection: N/A Certification: CE, FCC Class A, UKCA, E13 Operating Temperature: -30°C to 60°C TPM: TPM 2.0, optional	Ingress Protection: IP65 Certification: CE, FCC Class A, UKCA, E13 Operating Temperature: -30°C to 60°C TPM: TPM 2.0, optional	Ingress Protection: IP65 Certification: CE, FCC Class A, UKCA, E13 Operating Temperature: -30°C to 60°C TPM: TPM 2.0, optional
Others	OS: Win 10, Linux (Kernel 4.x) Dimensions (mm): 260.0 x 198.0 x 50.0	OS: Win 7/8/10, WES 7/8, WLinux (Kernel 4.x) Dimensions (mm): 260.0 x 196.0 x 66.5	OS: Win 7/8/10, WES 7/8, WLinux (Kernel 4.x) Dimensions (mm): 260.0 x 196.0 x 66.5	OS: Win 7/8/10, WES 7/8, WLinux (Kernel 4.x) Dimensions (mm): 260.0 x 198.0 x 66.5	OS: Win 7/8/10, WES 7/8, WLinux (Kernel 4.x) Dimensions (mm): 260.0 x 198.0 x 66.5



Railway Computer - Box PC/Panel PC

nROK/vROK Series Brief Product Introduction

Product Description

nROK series, railway computer, in an extended operating temperature range of -40 to 70°C certified EN50155 and IP65 protection depended on models. The SKU with PoE integrated all-in-one computer can also work as a PoE switch and power supply for PoE cameras. Wide-range power input SKU from 24 to 110VDC includes isolation and protection against power dips. Multiple Wi-Fi 6/6E

and 5G/LTE cellular networks handle the connectivity that provides uninterrupted internet access and more transmission bandwidth, vROK series, all in one railway open frame panel computer, is designed for human machine interface (HMI) and passenger information system aimed at railway onboard infotainment applications.



5G/LTE, Wi-Fi 6/6E, BT, CAN/OBD, GNSS + DR, POE, and multi-SIM integration



Front accessible SSD storage



Optional isolated 24~110VDC power input



Global navigation satellite system for precise and real-time location

Application

nROK: Communications hub, passenger information system, onboard video surveillance, digital radio data/voice transmission system, freight management system, rail analytics system, rail maintenance applications.

vROK: Human machine interface (HMI), passenger information system, infotainment.

Product Highlight



EN50155 certified system



Protection for voltage dips



M12 X-coded/D-coded PoE port for IP cameras



Open frame design railway panel computer

Railway Computer - Box PC

Model			
	VTC 1911-IPK	nROK 1020-A	nROK 1030-A
System			
CPU	Intel Atom® E3815, 1-core, 1.46GHz	Intel Atom® x5-E3930, 2-core, 1.3GHz	Intel Atom® x6211E, 2-core, 1.3GHz
Chipset	N/A	N/A	N/A
Memory	1 x DDR3L 1333 SO-DIMM, 2GB (default) up to 8GB	1 x DDR3L 1866 SO-DIMM, 4GB (default) up to 8GB	1 x DDR4 2666 SO-DIMM, 4GB (default) up to 3200MHz 32GB, in-band ECC support
Storage	1 x mSATA	1 x 2.5" SATA 3.0 SSD (9.5mm)	1 x 2.5" SATA 3.0 SSD (9.5mm)
Second Storage	1 x 2.5" SATA 3.0 SSD (9.5mm) or 1 x SATA 3.0 SATA DOM	1 x mSATA (occupied mini-PCIe socket)	1 x mSATA (occupied mini-PCIe socket)
Video Out	1 x VGA, 1 x HDMI (optional)	1 x VGA, 1 x HDMI	1 x VGA, 1 x HDMI
Audio	1 x Mic-in, 1 x Line-out (DB15)	1 x Mic-in, 1 x Line-out (M12)	1 x Mic-in, 1 x Line-out (DB9)
Ethernet	2 x Intel® 10/100/1000 (M12)	1 x Intel® 10/100/1000 (M12)	2 x Intel® 10/100/1000/2500 (M12)
I/O Interface			
PoE	N/A	N/A	N/A
USB	1 x USB 2.0	2 x USB 3.2 (Gen1)	1 x USB 3.2 (Gen2), 1 x USB 2.0
COM	2 x RS232, 1 x RS485	5 x RS232, 2 x RS485	2 x RS232 (Full)/422/485
DIO	3 x DI, 3 x DO	5 x Programmable DIO	5 x DI, 4 x DO
CAN Bus	1 x CAN Bus 2.0B (w/o isolation)	1 x CAN Bus 2.0B (w/o isolation)	1 x CAN Bus 2.0B (w/ isolation)
DC Output	N/A	12V (2A)	12V (2A)
SMBus	N/A	1	N/A
SIM Socket	2	1	2 (eSIM BOM optional)
WWAN	1	1	1
Expansion			
mini-PCIe Socket	- 1 x (USB 2.0, PCIe 2.0/SATA 2.0) - 1 x (USB 2.0) for LTE	- 1 x (USB 2.0, PCIe 2.0/SATA 3.0) - 1 x (USB 2.0) for LTE	- 1 x (USB 2.0, PCIe 3.0/SATA 3.0)
M.2 Socket	N/A	N/A	- 1 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen 2)) for LTE/5G - 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0 x2). BOM option to 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0, PCIe 3.0)
GNSS	Onboard u-blox NEO-M8N	VI0B-GPS-02 module (u-blox NEO-M8N)	VI0B-GPS-06 module (u-blox NEO-M9N)
Power			
Power Input	DC 9V to 36V	DC 24V (w/o isolation)	DC 24V (w/o isolation)
Backup Battery	N/A	N/A	N/A
Environment			
Ingress Protection	IP67	N/A	N/A
Certification	CE, FCC Class A, UKCA, E13, EN50155	CE, FCC Class A, UKCA, EN50155	CE, FCC Class A, UKCA, EN45545-2, EN50155
Operating Temperature	-40°C to 70°C (OT4)	-40°C to 70°C (OT4)	-40°C to 70°C (OT4)
TPM	TPM 2.0	TPM 2.0	TPM 2.0
Others			
OS	Win 7/8/10, WES 7, Linux (Kernel 4.x)	Win 10, Linux (Kernel 4.x)	Win 10/11 64-bit, Linux (Kernel 5.x)
Dimensions (mm)	185.0 x 167.0 x 56.5	185.0 x 120.0 x 45.0	185.0 x 120.0 x 50.0



Model			
	nROK 1031-A	nROK 1031-AC2	VTC 6210-R
System			
CPU	Intel Atom® x6413E, 4-core, 1.5GHz	Intel Atom® x6413E, 4-core, 1.5GHz	Intel Atom® E3845, 4-core, 1.91GHz
Chipset	N/A	N/A	N/A
Memory	1 x DDR4 2666 SO-DIMM, 4GB (default) up to 3200MHz 32GB, in-band ECC support	1 x DDR3 1333 SO-DIMM, 2GB (default) up to 8GB	1 x DDR3 1333 SO-DIMM, 2GB (default) up to 8GB
Storage	1 x 2.5" SATA 3.0 SSD (9.5mm)	1 x 2.5" SATA 3.0 SSD (9.5mm)	1 x 2.5" SATA 2.0 SSD (removable, 9.5mm)
Second Storage	1 x M.2 2280 Key M SSD (SATA 3.0)	1 x M.2 2280 Key M SSD (SATA 3.0)	1 x CFast (external accessible)
Video Out	1 x VGA, 1 x HDMI	1 x VGA, 1 x HDMI	1 x VGA, 1 x DP
Audio	1 x Mic-in, 1 x Line-out (DB9)	1 x Mic-in, 1 x Line-out (DB9)	2 x Mic-in, 2 x Line-out (Phone Jack)
Ethernet	1 x Intel® 10/100/1000/2500 1 x 10/100/1000 (M12)	1 x Intel® 10/100/1000/2500 1 x 10/100/1000 (M12)	2 x Intel® 10/100/1000 (M12)
I/O Interface			
PoE	N/A	2 x M12 Independent Intel® 10/100/1000/2500 (802.3af/at). Total 60W	N/A
USB	1 x M12 with 2 x USB 2.0 signal, 1 x USB 2.0, 1 x USB 3.2 (Gen 2)	1 x M12 with 2 x USB 2.0 signal, 1 x USB 2.0, 1 x USB 3.2 (Gen 2)	1 x M12 with 2 x USB 2.0 signal, 1 x USB 3.2 (Gen1)
COM	1 x RS232 (Full)/422/485, 1 x RS232, 2 x RS485	1 x RS232 (Full)/422/485, 1 x RS232, 2 x RS485	2 x RS232 (Full), 1 x RS422/485. (w/ isolation)
DIO	5 x DI, 4 x DO	5 x DI, 4 x DO	4 x DI, 4 x DO (w/ isolation)
CAN Bus	1 x CAN Bus 2.0B (w/ isolation)	1 x CAN Bus 2.0B (w/ isolation)	1 x CAN Bus 2.0B (w/ isolation)
DC Output	12V (2A)	12V (2A)	N/A
SMBus	N/A	N/A	N/A
SIM Socket	2 (eSIM BOM optional)	2 (eSIM BOM optional)	3
WWAN	1	1	2
Expansion			
mini-PCIe Socket	- 1 x (USB 2.0, PCIe 3.0). BOM option to 1 x M.2 3042 Key B socket (USB 2.0, USB 3.2 (Gen 2)) for LTE/5G NR	- 1 x (USB 2.0, PCIe 3.0). BOM option to 1 x M.2 3042 Key B socket (USB 2.0, USB 3.2 (Gen 2)) for LTE/5G NR	- 1 x (USB 2.0, PCIe 2.0) - 1 x (USB 2.0, PCIe 2.0) for LTE - 1 x (USB 2.0) for LTE
M.2 Socket	- 1 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen 2)) for LTE/5G - 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0 x2). BOM option to 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0, PCIe 3.0)	- 1 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen 2)) for LTE/5G - 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0 x2). BOM option to 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0, PCIe 3.0)	N/A
GNSS	VI0B-GPS-06 module (u-blox NEO-M9N)	VI0B-GPS-06 module (u-blox NEO-M9N)	VI0B-GPS-02 module (u-blox NEO-M8N)
Power			
Power Input	DC 24V (w/o isolation)	DC 24V (w/o isolation)	DC 24/36V (w/o isolation), 110V (w/ isolation)
Backup Battery	N/A	N/A	N/A
Environment			
Ingress Protection	N/A	N/A	N/A
Certification	CE, FCC Class A, UKCA, EN50155	CE, FCC Class A, UKCA, EN50155	CE, FCC Class A, UKCA, EN50155
Operating Temperature	-40°C to 70°C (OT4)	-40°C to 70°C (OT4)	-40°C to 70°C (OT4)
TPM	TPM 2.0	TPM 2.0	N/A
Others			
OS	Win 10/11 64-bit, Linux (Kernel 5.x)	Win 10/11 64-bit, Linux (Kernel 5.x)	Win 7/8/10, WES 7, Linux (Kernel 4.x)
Dimensions (mm)	180.0 x 180.0 x 60.0	180.0 x 180.0 x 60.0	260.0 x 176.0 x 70.0



Railway Computer - Box PC

Model			
	nROK 6221	nROK 6221-IP	nROK 6222-AC4S
System			
CPU	Intel Atom® x7-E3950, 4-core, 1.6GHz	Intel Atom® x7-E3950, 4-core, 1.6GHz	Intel Atom® x7-E3950, 4-core, 1.6GHz
Chipset	N/A	N/A	N/A
Memory	1 x DDR3L 1866 SO-DIMM, 4GB (default) up to 8GB	1 x DDR3L 1866 SO-DIMM, 4GB (default) up to 8GB	1 x DDR3L 1866 SO-DIMM, 4GB (default) up to 8GB
Storage	1 x 2.5" SATA 3.0 SSD (removable, 15mm)	1 x 2.5" SATA 3.0 SSD (removable, 15mm)	2 x 2.5" SATA 3.0 SSD (removable, 15mm)
Second Storage	1 x CFast (external accessible, default) or 1 x mSATA (occupied CFast, BOM optional)	1 x CFast (external accessible, default) or 1 x mSATA (occupied CFast, BOM optional)	1 x SD (external accessible), 1 x internal USB DOM
Video Out	2 x VGA, 1 x HDMI	2 x VGA	1 x VGA, 2 x HDMI
Audio	1 x Mic-in, 2 x Line-out (DB9)	1 x Mic-in, 1 x Line-out (M8)	1 x Mic-in, 1 x Line-out (M8)
Ethernet	2 x Intel® 10/100/1000 (M12). (additional 1 x Intel® 10/100/1000 (M12), BOM optional)	2 x Intel® 10/100/1000 (M12). (additional 1 x Intel® 10/100/1000 (M12), BOM optional)	1 x Intel® 10/100/1000 (M12)
I/O Interface			
PoE	N/A	N/A	4 x M12 Intel® 10/100/1000 (802.3af/at). Total 60W
USB	1 x M12 with 2 x USB 2.0 signal, 1 x USB 2.0, 1 x USB 3.2 (Gen1)	1 x M12 with 2 x USB 2.0 signal, 1 x USB 3.2 (Gen1)	1 x M12 with 2 x USB 2.0 signal, 1 x USB 3.2 (Gen1)
COM	1 x RS232 (Full), 1 x RS232, 1 x RS485. (w/ isolation)	1 x RS232 (Full), 1 x RS232, 1 x RS485. (w/ isolation)	1 x RS232 (Full), 1 x RS232, 1 x RS422/485. (w/ isolation)
DIO	4 x DI, 4 x DO (w/ isolation)	4 x DI, 3 x DO (w/ isolation)	4 x DI, 4 x DO (w/ isolation)
CAN Bus	1 x CAN Bus 2.0B (w/ isolation)	1 x CAN Bus 2.0B (w/ isolation)	1 x CAN Bus 2.0B (w/ isolation)
DC Output	N/A	N/A	N/A
SIM Socket	6 (BOM option up to 8, eSIM BOM optional)	6 (BOM option up to 8, eSIM BOM optional)	2 (eSIM BOM optional)
WWAN	3 (BOM option up to 4)	3 (BOM option up to 4)	1
Expansion			
mini-PCIe Socket	- 1 x (USB 2.0, PCIe 2.0) - 1 x (USB 2.0, PCIe 2.0). BOM option to 1 x mini-PCIe (USB 2.0) for LTE - 1 x (USB 2.0) for LTE	- 1x(USB2.0,PCIe2.0) - 1x(USB2.0,PCIe2.0). BOM option to 1 x mini-PCIe (USB 2.0) for LTE - 1x(USB2.0)forLTE	- 2 x (USB 2.0, PCIe 2.0) - 1 x (USB 2.0) for LTE. BOM option to 1 x M.2 3042 Key B (USB 2.0, USB 3.2 (Gen1)) LTE/5G
M.2 Socket	- 1 x M.2 3042 Key B (USB 2.0, USB 3.2 (Gen 1))for LTE/5G - 1 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen 1)) for LTE/5G	- 1xM.23042KeyB - (USB 2.0, USB 3.2 (Gen 1)) for LTE/5G - 1xM.23042/3050/3052Key B (USB 2.0, USB 3.2 (Gen 1)) for LTE/5G	- 1 x M.2 3042 Key B (USB 2.0, USB 3.2 (Gen 1)) for LTE/5G (BOM optional)
GNSS	VIOB-GPS-02 module (u-blox NEO-M8N)	VIOB-GPS-02 module (u-blox NEO-M8N)	u-blox-NEO-M8N onboard
Power			
Power Input	DC 24/36V (w/o isolation), DC 24/110V (w/ isolation, optional)	DC 24 (w/ isolation), DC 24/36V (w/o isolation, optional), DC 110V (w/ isolation, optional)	DC 24/36V (w/o isolation) DC 24/110V (w/ isolation, external power kit, optional)
Backup Battery	N/A	N/A	N/A
Ingress Protection	N/A	IP65	N/A
Environment			
Certification	CE, FCC Class A, UKCA, EN50155	CE, FCC Class A, UKCA, EN50155	CE, FCC Class A, UKCA, EN50155
Operating Temperature	-40°C to 70°C (OT4)	-40°C to 70°C (OT4)	-40°C to 70°C (OT4)
TPM	TPM 2.0, optional	TPM 2.0, optional	TPM 2.0, optional
Others			
OS	Win 10 64-bit, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)	Win 10, Linux (Kernel 4.x)
Dimensions (mm)	260.0 x 196.0 x 70.0	260.0 x 198.0 x 70.0	260.0 x 196.0 x 66.5



Model			
	nROK 6231-A	nROK 6232-AC4S	nROK 6232-AC4S-BAT
System			
CPU	Intel Atom® x7433RE, 4-core, 1.5GHz	Intel Atom® x7433RE, 4-core, 1.5GHz	Intel Atom® x7433RE, 4-core, 1.5GHz
Chipset	N/A	N/A	N/A
Memory	1 x DDR5 4800 SO-DIMM, 8GB (default) up to 16GB, in-band ECC support	1 x DDR5 4800 SO-DIMM, 8GB (default) up to 16GB, in-band ECC support	1 x DDR5 4800 SO-DIMM, 8GB (default) up to 16GB, in-band ECC support
Storage	1 x 2.5" SATA 3.0 SSD (removable, 9.5mm)	eMMC 5.1, 64GB	eMMC 5.1, 64GB
Second Storage	1 x mSATA (occupied mini-PCIe socket)	2 x 2.5" SATA 3.0 SSD (removable, 15mm)	1 x 2.5" SATA 3.0 SSD (removable, 15mm), 1 x M.2 2242 Key B (SATA)
Video Out	1 x VGA, 1 x HDMI, 1 x DP	1 x VGA, 1 x HDMI, 1 x DP	1 x VGA, 1 x HDMI, 1 x DP
Audio	1 x Mic-in, 1 x Line-in, 1 x Line-out	1 x Mic-in, 1 x Line-in, 1 x Line-out	1 x Mic-in, 1 x Line-in, 1 x Line-out
Ethernet	2 x Intel® 10/100/1000/2500	1 x Intel® 10/100/1000/2500	1 x Intel® 10/100/1000/2500
I/O Interface			
PoE	N/A	4 x Intel® 2.5GbE (w/ 802.3af/at/bt). Total 90W	4 x Intel® 2.5GbE (w/ 802.3af/at/bt). Total 90W
USB	2 x USB 2.0, 2 x USB 3.2 (Gen2)	2 x USB 2.0, 2 x USB 3.2 (Gen2)	2 x USB 2.0, 2 x USB 3.2 (Gen2)
COM	2 x RS232(Full)/422/485, 1 x RS232 (Full)	2 x RS232(Full)/422/485, 1 x RS232, 1 x RS422/485	2 x RS232(Full)/422/485, 1 x RS232, 1 x RS422/485
DIO	4 x DI, 4 x DO	4 x DI, 4 x DO	4 x DI, 4 x DO
CAN Bus	1 x CAN FD (w/ isolation)	1 x CAN FD (w/ isolation)	1 x CAN FD (w/ isolation)
DC Output	12V (2A)	12V (2A)	12V (2A)
SIM Socket	8 (eSIM BOM optional)	4 (eSIM BOM optional)	4 (eSIM BOM optional)
WWAN	3 (BOM option up to 4)	2	2
Expansion			
mini-PCIe Socket	- 1 x (USB 2.0, SATA 3.0/PCIe 3.0) default for mSATA, BIOS select (USB 2.0) for LTE, BOM option (USB 2.0, PCIe 3.0) for WiFi - 1 x (USB 2.0, PCIe 3.0) for WiFi, BOM option to 1 x M.2 3052 Key B (USB 2.0, USB 3.2 Gen 2x1) for LTE/5G	- 1 x (USB 2.0, PCIe 3.0), BOM optional to 1 x M.2 3052 Key B (USB 2.0, USB 3.2 Gen 2) for LTE/5G	- 1 x (USB 2.0, PCIe 3.0), BOM optional to 1 x M.2 3052 Key B (USB 2.0, USB 3.2 Gen 2) for LTE/5G
M.2 Socket	- 2 x M.2 3042/3052 Key B (USB 2.0, USB 3.2) for LTE/5G - 1 x M.2 2230 Key E (PCIe 3.0 x 1, USB 2.0) for Wi-Fi. BOM option mPCIe (PCIe 3.0 x 1, USB2.0) for Hailo module	- 1 x M.2 3042/3052 Key B (USB 2.0, USB 3.2(Gen2)) for LTE/5G - 1 x M.2 2230 Key E (PCIe 3.0 x 1, USB 2.0), BOM optional mPCIe (PCIe 3.0 x 1, USB2.0) for Hailo module	- 1 x M.2 3042/3052 Key B (USB 2.0, USB 3.2(Gen2)) for LTE/5G - 1 x M.2 2230 Key E (PCIe 3.0 x 1, USB 2.0), BOM optional mPCIe (PCIe 3.0 x 1, USB2.0) for Hailo module
GNSS	VIOB-GPS-06 module (u-blox NEO-M9N)	VIOB-GPS-07 module (u-blox NEO-M9N)	VIOB-GPS-07 module (u-blox NEO-M9N)
Power			
Power Input	DC 24V (w/o isolation), DC 24/110V (w/ isolation, optional)	DC 24V (w/o isolation)	DC 24V (w/o isolation)
Backup Battery	N/A	N/A	YES
Ingress Protection	N/A	N/A	N/A
Environment			
Certification	CE, FCC Class A, UKCA, EN50155, EN45545-2	CE, FCC Class A, UKCA, EN50155, EN45545-2	CE, FCC Class A, UKCA, EN50155, EN45545-2
Operating Temperature	-40°C to 70°C (OT4)	-40°C to 70°C	-40°C to 70°C
TPM	TPM 2.0	TPM 2.0	TPM 2.0
Others			
OS	Win 10/11, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)
Dimensions (mm)	260.0 x 196.0 x 70.0	260.0 x 196.0 x 66.5	260.0 x 196.0 x 66.5

Railway Computer - Box PC

Model		 nROK 6232-WIC4S	 nROK 7251-7A	 nROK 7251-7C4	
System	CPU	Intel Atom® x7433RE, 4-core, 1.5GHz	Intel® Core™ i7-9700TE, 8-core, 1.8GHz	Intel® Core™ i7-9700TE, 8-core, 1.8GHz	
	Chipset	N/A	Intel® Q370	Intel® Q370	
	Memory	1 x DDR5 4800 SO-DIMM, 8GB (default) up to 16GB, in-band ECC support	2 x DDR4 2666 SO-DIMM, 8GB (default) up to 64GB	2 x DDR4 2666 SO-DIMM, 8GB (default) up to 64GB	
	Storage	eMMC 5.1, 64GB	2 x 2.5" SATA 3.0 SSD (removable, 15mm)	2 x 2.5" SATA 3.0 SSD (removable, 15mm)	
I/O Interface	Second Storage	1 x 2.5" SATA 3.0 SSD (removable, 15mm), 1 x M.2 2242 Key B (SATA)	2 x mSATA (occupied mini-PCIe socket)	2 x mSATA (occupied mini-PCIe socket)	
	Video Out	1 x VGA, 1 x HDMI, 1 x DP	1 x VGA, 1 x HDMI	1 x VGA, 1 x HDMI	
	Audio	1 x Mic-in, 1 x Line-in, 1 x Line-out	1 x Mic-in, 1 x Line-out (M8)	1 x Mic-in, 1 x Line-out (M8)	
	Ethernet	1 x Intel® 10/100/1000/2500	2 x Intel® 10/100/1000 (M12)	1 x Intel® 10/100/1000 (M12)	
	PoE	4 x Intel® 2.5GbE (w/ 802.3af/at/bt). Total 90W	N/A	4 x M12 independent Intel® 10/100/1000 (802.3af/at). Total 60W	
	USB	2 x USB 2.0, 2 x USB 3.2 (Gen2)	1 x M12 with 2 x USB 2.0 signal, 4 x USB 3.2 (Gen2)	1 x M12 with 2 x USB 2.0 signal, 4 x USB 3.2 (Gen2)	
	COM	2 x RS232(full)/422/485, 1 x RS232, 1 x RS422/485	2 x RS232 (Full), 1 x RS232 (Full)/422/485. (w/ isolation)	2 x RS232 (Full), 1 x RS232 (Full)/422/485. (w/ isolation)	
	DIO	4 x DI, 4 x DO	4 x DI, 4 x DO (w/ isolation)	4 x DI, 4 x DO (w/ isolation)	
	CAN Bus	1 x CAN FD (w/ isolation)	N/A	N/A	
	DC Output	12V (2A)	N/A	N/A	
	SIM Socket	4 (eSIM BOM optional)	6 (BOM option up to 8, eSIM BOM optional)	6 (BOM option up to 8, eSIM BOM optional)	
	WWAN	2	3 (BOM option up to 4)	3 (BOM option up to 4)	
	Expansion	mini-PCIe Socket	- 1 x (USB 2.0, PCIe 3.0), BOM optional to 1 x M.2 3052 Key B (USB 2.0, USB 3.2 Gen2) for LTE/5G	- 1 x (USB 2.0, PCIe 3.0/SATA 3.0) - 1 x (USB 2.0, PCIe 3.0/SATA 3.0). BOM option to 1 x mini-PCIe (USB 2.0) for LTE - 1 x (USB 2.0) for LTE. BOM option to 1 x M.2 3042 Key B (USB 2.0, USB 3.2 (Gen2)) for LTE/5G	- 1 x (USB 2.0, PCIe 3.0/SATA 3.0) - 1 x (USB 2.0, PCIe 3.0/SATA 3.0). BOM option to 1 x mini-PCIe (USB 2.0) for LTE - 1 x (USB 2.0) for LTE. BOM option to 1 x M.2 3042 Key B (USB 2.0, USB 3.2 (Gen2)) for LTE/5G
		M.2 Socket	- 1 x M.2 3042/3052 Key B (USB 2.0, USB 3.2(Gen2)) for LTE/5G - 1 x M.2 2230 Key E (PCIe 3.0 x 1, USB 2.0), BOM optional mPCIe (PCIe 3.0 x 1, USB2.0) for Hailo module	- 2 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen2)) for LTE/5G	- 2 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen2)) for LTE/5G
	Power	GNSS	VIOB-GPS-07 module (u-blox NEO-M9N)	VIOB-GPS-02 module (u-blox NEO-M8N)	VIOB-GPS-02 module (u-blox NEO-M8N)
		Power Input	DC 24 to 110V (w/ isolation)	DC 24V (w/o isolation)	DC 24V (w/o isolation)
		Backup Battery	N/A	N/A	N/A
	Environment	Ingress Protection	N/A	N/A	N/A
		Certification	CE, FCC Class A, UKCA, EN50155, EN45545-2	CE, FCC Class A, UKCA, EN50155	CE, FCC Class A, UKCA, EN50155
Operating Temperature		-40°C to 70°C	-40°C to 70°C (OT4)	-40°C to 70°C (OT4)	
Others	TPM	TPM 2.0	TPM 2.0	TPM 2.0	
	OS	Win 10/11, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)	
	Dimensions (mm)	260.0 x 196.0 x 66.5	260.0 x 256.0 x 84.0	260.0 x 256.0 x 84.0	



Model		 nROK 7251-WI-7C4IP	 nROK 7252-AC8S	 nROK 7252-WI2-C8S	
System	CPU	Intel® Core™ i7-9700TE, 8-core, 1.8GHz	8/9th Gen Intel® Core™/Xeon® (AI Hailo-8™ onboard option)	8/9th Gen Intel® Core™/Xeon® (AI Hailo-8™ onboard option)	
	Chipset	Intel® Q370	Intel® C246	Intel® C246	
	Memory	2 x DDR4 2666 SO-DIMM, 8GB (default) up to 64GB	2 x DDR4 2666 SO-DIMM, up to 64GB	2 x DDR4 2666 SO-DIMM, up to 64GB	
	Storage	2 x 2.5" SATA 3.0 SSD (removable, 15mm)	4 x 2.5" SATA 3.0 SSD (removable, 15mm)	2 x 2.5" SATA 3.0 SSD (removable, 15mm)	
I/O Interface	Second Storage	2 x mSATA (occupied mini-PCIe socket)	2 x mSATA (occupied mini-PCIe socket) 1 x Removable SD 3.0	2 x mSATA (occupied mini-PCIe socket) 1 x Removable SD 3.0	
	Video Out	1 x VGA	1 x VGA, 2 x HDMI	1 x VGA, 2 x HDMI	
	Audio	1 x Mic-in, 1 x Line-out (M8)	1 x Mic-in, 2 x Line-out (DB9)	1 x Mic-in, 2 x Line-out (DB9)	
	Ethernet	1 x Intel® 10/100/1000 (M12)	2 x Intel® 10/100/1000 (M12)	2 x Intel® 10/100/1000 (M12)	
	PoE	4 x M12 independent Intel® 10/100/1000 (802.3af/at). Total 60W	8 x M12 10/100/1000 (802.3af/at). Total 60W	8 x M12 10/100/1000 (802.3af/at). Total 60W	
	USB	1 x M12 with 2 x USB 2.0 signal, 4 x USB 3.2 (Gen2)	1 x M12 with 2 x USB 2.0 signal, 4 x USB 3.2 (Gen2)	1 x M12 with 2 x USB 2.0 signal, 4 x USB 3.2 (Gen2)	
	COM	2 x RS232 (Full), 1 x RS232 (Full)/422/485. (w/ isolation)	2 x RS232 (Full), 1 x RS232 (Full)/422/485. (w/ isolation)	2 x RS232 (Full), 1 x RS232 (Full)/422/485. (w/ isolation)	
	DIO	4 x DI, 4 x DO (w/ isolation)	4 x DI, 4 x DO (w/ isolation)	4 x DI, 4 x DO (w/ isolation)	
	CAN Bus	N/A	1 x CAN Bus 2.0B (w/ isolation)	1 x CAN Bus 2.0B (w/ isolation)	
	DC Output	N/A	N/A	N/A	
	SIM Socket	6 (BOM option up to 8, eSIM BOM optional)	6 (BOM option up to 8, eSIM BOM optional)	6 (BOM option up to 8, eSIM BOM optional)	
	WWAN	3 (BOM option up to 4)	3 (BOM option up to 4)	3 (BOM option up to 4)	
	Expansion	mini-PCIe Socket	- 1 x (USB 2.0, PCIe 3.0/SATA 3.0) - 1 x (USB 2.0, PCIe 3.0/SATA 3.0). BOM option to 1 x mini-PCIe (USB 2.0) for LTE - 1 x (USB 2.0) for LTE. BOM option to 1 x M.2 3042 Key B (USB 2.0, USB 3.2 (Gen2)) for LTE/5G	- 1 x (USB 2.0, PCIe 3.0/SATA 3.0) - 1 x (USB 2.0, PCIe 3.0/SATA 3.0). BOM option to 1 x mini-PCIe (USB 2.0, USB 3.2 (Gen1)) for LTE/5G - 1 x (USB 2.0) for LTE. BOM option to 1 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen2)) for LTE/5G	- 1 x (USB 2.0, PCIe 3.0/SATA 3.0) - 1 x (USB 2.0, PCIe 3.0/SATA 3.0). BOM option to 1 x mini-PCIe (USB 2.0, USB 3.2 (Gen1)) for LTE/5G - 1 x (USB 2.0) for LTE. BOM option to 1 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen2)) for LTE/5G
		M.2 Socket	- 2 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen2)) for LTE/5G	- 2 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen2)) for LTE/5G	- 2 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen2)) for LTE/5G
	Power	GNSS	VIOB-GPS-02 module (u-blox NEO-M8N)	VIOB-GPS-02 module (u-blox NEO-M8N)	VIOB-GPS-02 module (u-blox NEO-M8N)
		Power Input	DC 24V to 110V (w/ isolation)	DC 24/36V (w/o isolation)	DC 24V to 110V (w/ isolation, 3-second protection against temporary voltage dips)
		Backup Battery	N/A	N/A	N/A
	Environment	Ingress Protection	IP65	N/A	N/A
		Certification	CE, FCC Class A, UKCA, EN50155	CE, FCC Class A, UKCA, EN50155	CE, FCC Class A, UKCA, EN50155
Operating Temperature		-40°C to 70°C (OT4)	-40°C to 70°C (OT4)	-40°C to 70°C (OT4)	
Others	TPM	TPM 2.0	TPM 2.0	TPM 2.0	
	OS	Win 10/11, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)	
	Dimensions (mm)	260.0 x 256.0 x 110.0	260.0 x 266.0 x 110.0	260.0 x 266.0 x 110.0	



Railway Computer - Box PC

Model	 NEW	 NEW	 NEW
	nROK 7270-A	nROK 7270-AC4	nROK 7271-WI
System			
CPU	Intel® Core™ 12th/13th Gen	Intel® Core™ 12th/13th Gen	Intel® Core™ 12th/13th Gen
Chipset	Intel® R680E	Intel® R680E	Intel® R680E
Memory	2 x DDR5 4800 SO-DIMM, up to 64GB, ECC support	2 x DDR5 4800 SO-DIMM, up to 64GB, ECC support	2 x DDR5 4800 SO-DIMM, up to 64GB, ECC support
Storage	2 x 2.5" SATA 3.0 SSD (removable, 15mm)	2 x 2.5" SATA 3.0 SSD (removable, 15mm)	2 x 2.5" SATA 3.0 SSD (removable, 15mm)
Second Storage	1 x mSATA (occupied mini-PCIe socket) 2 x M.2 Key B (occupied M.2 socket) 1 x microSD card slot, SDXC v3.01	1 x mSATA (occupied mini-PCIe socket) 2 x M.2 Key B (occupied M.2 socket) 1 x microSD card slot, SDXC v3.01	1 x mSATA (occupied mini-PCIe socket) 2 x M.2 Key B (occupied M.2 socket) 1 x microSD card slot, SDXC v3.01
Video Out	1 x VGA, 1 x HDMI	1 x VGA, 1 x HDMI	1 x VGA, 1 x HDMI
Audio	1 x Mic-in, 1 x Line-out (M8)	1 x Mic-in, 1 x Line-out (M8)	1 x Mic-in, 1 x Line-out (M8)
Ethernet	2 x Intel® 10/100/1000/2500 (M12, WoL support)	1 x Intel® 10/100/1000/2500 (M12, WoL support)	2 x Intel® 10/100/1000/2500 (M12, WoL support)
PoE	N/A	4 x independent Intel® 2.5GbE (802.3af/at). Total 60W	N/A
USB	1 x M12 with 2 x USB 2.0 signal, 2 x USB 3.2 (Gen2)	1 x M12 with 2 x USB 2.0 signal, 2 x USB 3.2 (Gen2)	1 x M12 with 2 x USB 2.0 signal, 2 x USB 3.2 (Gen2)
COM	2 x RS232 (Full)/422/485. (w/ isolation)	2 x RS232 (Full)/422/485. (w/ isolation)	2 x RS232 (Full)/422/485. (w/ isolation)
DIO	4 x DI, 4 x DO (w/ isolation)	4 x DI, 4 x DO (w/ isolation)	4 x DI, 4 x DO (w/ isolation)
CAN Bus	2 x CAN FD (w/ isolation)	2 x CAN FD (w/ isolation)	2 x CAN FD (w/ isolation)
DC Output	N/A	N/A	N/A
SIM Socket	4 (eSIM BOM optional)	4 (eSIM BOM optional)	4 (eSIM BOM optional)
WWAN	2	2	2
mini-PCIe Socket	- 1 x (USB 2.0, PCIe 3.0/SATA 3.0)	- 1 x (USB 2.0, PCIe 3.0/SATA 3.0)	- 1 x (USB 2.0, PCIe 3.0/SATA 3.0)
M.2 Socket	- 2 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen2), SATA 3.0) for LTE/5G - 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0 x2). BOM option to 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0, PCIe 3.0)	- 2 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen2), SATA 3.0) for LTE/5G - 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0 x2). BOM option to 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0, PCIe 3.0)	- 2 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen2), SATA 3.0) for LTE/5G - 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0 x2). BOM option to 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0, PCIe 3.0)
GNSS	VIOB-GPS-06 module (u-blox NEO-M9N)	VIOB-GPS-06 module (u-blox NEO-M9N)	VIOB-GPS-06 module (u-blox NEO-M9N)
Power			
Power Input	DC 24/36V (w/o isolation)	DC 24/36V (w/o isolation)	DC 24V to 110V (w/ isolation, optional 3-second protection against temporary voltage dips)
Backup Battery	N/A	N/A	N/A
Environment			
Ingress Protection	N/A	N/A	N/A
Certification	CE, FCC Class A, UKCA, EN50155, EN45545-2	CE, FCC Class A, UKCA, EN50155, EN45545-2	CE, FCC Class A, UKCA, EN50155
Operating Temperature	-35°C to 70°C (OT3)	-35°C to 70°C (OT3)	-35°C to 70°C (OT3)
TPM	TPM 2.0	TPM 2.0	TPM 2.0
OS	Win 10/11, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)
Dimensions (mm)	260.0 x 210.0 x 80.0	260.0 x 210.0 x 80.0	260.0 x 210.0 x 110.0



Railway Computer - Panel PC

Model	 NEW
	nROK 7271-WIC4
System	
CPU	Intel® Core™ 12th/13th Gen
Chipset	Intel® R680E
Memory	2 x DDR5 4800 SO-DIMM, up to 64GB, ECC support
Storage	2 x 2.5" SATA 3.0 SSD (removable, 15mm)
Second Storage	1 x mSATA (occupied mini-PCIe socket) 2 x M.2 Key B (occupied M.2 socket) 1 x microSD card slot, SDXC v3.01
Video Out	1 x VGA, 1 x HDMI
Audio	1 x Mic-in, 1 x Line-out (M8)
Ethernet	1 x Intel® 10/100/1000/2500 (M12, WoL support)
PoE	4 x Independent Intel® 2.5GbE (802.3af/at). Total 60W
USB	1 x M12 with 2 x USB 2.0 signal, 2 x USB 3.2 (Gen2)
COM	2 x RS232 (Full)/422/485. (w/ isolation)
DIO	4 x DI, 4 x DO (w/ isolation)
CAN Bus	2 x CAN FD (w/ isolation)
DC Output	N/A
SIM Socket	4 (eSIM BOM optional)
WWAN	2
mini-PCIe Socket	- 1 x (USB 2.0, PCIe 3.0/SATA 3.0)
M.2 Socket	- 2 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen2), SATA 3.0) for LTE/5G - 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0 x2). BOM option to 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0, PCIe 3.0)
GNSS	VIOB-GPS-06 module (u-blox NEO-M9N)
Power	
Power Input	DC 24V to 110V (w/ isolation, optional 3-second protection against temporary voltage dips)
Backup Battery	N/A
Environment	
Ingress Protection	N/A
Certification	CE, FCC Class A, UKCA, EN50155
Operating Temperature	-35°C to 70°C (OT3)
TPM	TPM 2.0
OS	Win 10/11, Linux (Kernel 4.x)
Dimensions (mm)	260.0 x 210.0 x 110.0



Model	
	vROK 3030
Display	
LCD Size	10.4" TFT LCD
Resolution	1024 x 768
Brightness (Typ.)	1200cd/m²
Contrast Ratio	900:1
View Angle	V: 85/85 H: 85/85
Brightness Adjustment	Auto via light sensor (BOM optional)
Touch Screen	Projected capacitive, anti-glare (BOM optional)
System	
CPU	Intel Atom® x6414RE, 4-core, 1.50GHz
Chipset	N/A
Memory	1 x DDR4 2666 SO-DIMM, 4GB (default) up to 32GB
Storage	1 x mSATA (occupied mini-PCIe socket) 1 x M.2 2280 Key M NVMe SSD (PCIe 3.0 x1, SATA 3.0)
Speaker	N/A
Control Button	BOM optional
Video Out	1 x HDMI, 1 x DP
Video Input	4 x CVBS
Audio	1 x Line-in, 2 x Line-out (DB9)
Ethernet	2 x Intel® 10/100/1000/2500 (M12)
PoE	Optional
USB	1 x M12 with 2 x USB 2.0 signal, 1 x USB 3.2 (Gen 2)
COM	2 x RS232 (Full)/422/485
DIO	4 x DI, 2 x DO (w/ isolation)
CAN Bus	1 x CAN Bus 2.0B (w/ isolation)
SIM Socket	2
WWAN	1
mini-PCIe Socket	- 1 x (USB 2.0, PCIe 3.0/SATA 3.0)
M.2 Socket	- 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0, PCIe 3.0) - 1 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen 2)) for LTE/5G
GNSS	VIOB-GPS-06 module (u-blox NEO-M9N)
Power	
Power Input	DC 24/36V (w/o isolation) DC 24/110V (w/ isolation, optional)
Back Up Battery	N/A
Ingress Protection	N/A
Environment	
Certification	CE, FCC Class A, UKCA, EN50155
Operating Temperature	-30°C to 70°C (OT3), w/o PoE -30°C to 60°C (OT1), w/ PoE
TPM	TPM 2.0
OS	Win 10/11, Linux (Kernel 4.x)
Mounting	VESA 75
Others	
Dimensions (mm)	309.0 x 230.6 x 67.7



Vehicle Network Switch

VES Series Brief Product Introduction

Product Description

VES Series is the unmanaged mobile vehicle and railway PoE switch that ensures stable network service for telematics applications. Enclosed in a fanless rugged chassis, they support a wide voltage input range, fully

operable under shock, vibration, and a harsh temperature range. The reliable mobile vehicle and railway PoE switch is certified with E-Mark and EN50155.

 EN50155 and E-Mark certification

 M12 X-coded LAN connector

 -40~70°C operating temperature

 Compact and ruggedized enclosure design

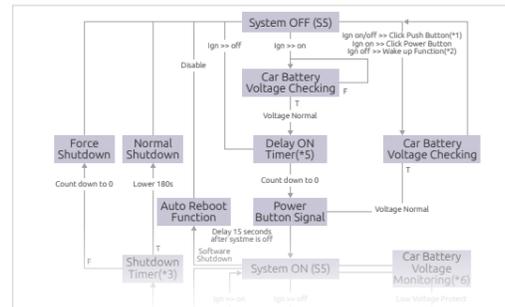
Application

- Video surveillance
- Wireless gateway
- Passenger infotainment system

Product Highlight



Dedicated for onboard vehicle/train systems



Ignition power management: power on/off delay, wide voltage input 9~36VDC, low voltage protection



Ultra-rugged enclosure, comply with MIL-STD-810H against vibration and shock impact



Rich 4/8-port IEEE 802.3af/at compliant PoE, up to 30W/port

Model				
	VES31-4S	VES31-8S	VES31-4SR	VES31-8SR
Architecture	Unmanaged GbE switch	Unmanaged GbE switch	Unmanaged GbE switch	Unmanaged GbE switch
PoE	4 x 10/100/1000 (w/ 802.3af/at). Total 120W.	8 x 10/100/1000 (w/ 802.3af/at). Total 120W.	4 x M12 10/100/1000 (w/ 802.3af/at). Total 120W.	8 x M12 10/100/1000 (w/ 802.3af/at). Total 120W.
Ethernet	2 x 10/100/1000	2 x 10/100/1000	2 x Intel® 10/100/1000 (M12)	2 x Intel® 10/100/1000 (M12)
LED	1 x Power indicator 4 x PoE indicator 1 x Low voltage protection indicator 8 x Active/link indicator	1 x Power indicator 8 x PoE indicator 1 x Low voltage protection indicator 12 x Active/link indicator	1 x Power indicator 4 x PoE indicator 1 x Low voltage protection indicator 6 x Active/link indicator	1 x Power indicator 8 x PoE indicator 1 x Low voltage protection indicator 10 x Active/link indicator
Power Input	DC 9V to 36V	DC 9V to 36V	DC 9V to 36V	DC 9V to 36V
Certification	CE, FCC Class B, UKCA, E13	CE, FCC Class B, UKCA, E13	CE, FCC Class B, UKCA, EN50155	CE, FCC Class B, UKCA, EN50155
Operating Temperature	-40°C to 70°C	-40°C to 70°C	-40°C to 70°C (OT4)	-40°C to 70°C (OT4)
Dimensions (mm)	167.0 x 140.0 x 52.0	167.0 x 140.0 x 52.0	167.0 x 140.0 x 62.0	167.0 x 140.0 x 62.0



Vehicle Mount Computer and Display

VMC and VMD Series Brief Product Introduction

Product Description

The VMC series is a durable vehicle mount computer suitable for warehouse, ports, logistics, and material handling markets. Its IP65 rating protects against water/dust damage and its sunlight readability ensures display visibility. Optional back-up battery preserves data when car power battery fails, while wide-range power input (9~60VDC) allows for use in various facilities, forklifts, and

vehicles. The VMD series is a tough TFT LCD monitor with a resistant or projected capacitive touchscreen, ideal for in-vehicle use. Its high-brightness display and automatic brightness control make it suitable for use in various lighting conditions. With an IP65 rating it is protected against water/dust damage, and its over 1000 nits display ensures excellent visibility.

 Full IP65 compliance

 Vibration and shock resistant

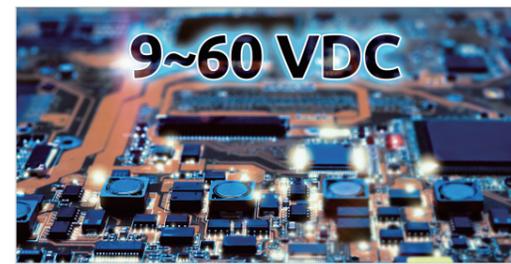
 5G/LTE, Wi-Fi 6/6E, BT, CAN/OBD, GNSS + DR, and multi-SIM integration

 E-Mark certification

Application

- Fleet management
- Warehouse management
- Port management applications

Product Highlight



Wide range power input 9~60VDC



Back-up battery provides uninterrupted power



Sunlight readability & high brightness



Impact protection IK08

Vehicle Mount Computer

Model			 Coming soon		
	VMC 110/111	VMC 1100-PRO	VMC 1110-PRO	VMC 220-PC1	
Display	LCD Size	7" TFT LCD	7" TFT LCD	7" TFT LCD	8" TFT LCD
	Resolution	1024 x 600	800 x 480	1024 x 600	1280 x 720
	Brightness (Typ.)	500cd/m ²	400cd/m ²	1200cd/m ²	1000cd/m ²
	Contrast Ratio	800:1	600:1	600:1	1000:1
	View Angle	V: 70/75 H: 75/75	V: 50/70 H: 70/70	V: 85/85 H: 85/85	V: 85/85 H: 85/85
System	Brightness Adjustment	Auto via light sensor	Auto via light sensor	Auto via light sensor	Auto via light sensor
	Touch Screen	4-wire resistive, anti-glare	4-wire resistive, anti-glare	4-wire resistive, anti-glare	Projected capacitive, anti-glare
	CPU	NXP i.MX6 Dual Lite, 2-core, 800 MHz	Intel Atom® E3825, 2-core, 1.33GHz	Intel Atom® x7211RE, 2-core, 1.0GHz	NXP i.MX 8M Quad, 4-core, 1.33GHz
	Chipset	N/A	N/A	N/A	N/A
	Memory	1 x 2GB DDR3L onboard	1 x DDR3L 1600 SO-DIMM, 4GB (default) up to 8GB	1 x DDR5 4800 SO-DIMM, 8GB (default) up to 16GB	1 x LPDDR4 2400 SDRAM 3GB onboard
I/O Interface	Storage	1 x 8GB eMMC 5.1 1 x Micro SD	1 x SATA 3.0 SATA DOM	1 x 128GB eMMC 5.1 1 x Micro SDXC 2 x M.2 Key B (SATA 3.0, occupied M.2 socket)	1 x 32GB eMMC 5.1 1 x Micro SD
	Speaker	2 x Built-in speaker	2 x Built-in speaker	2 x Built-in speaker	2 x Built-in speaker
	Control Button	F1~F5 function key 1 x Power button 2 x Brightness/volume control 1 x System reset button	F1~F5 function key 1 x Power button 2 x Brightness/volume control 1 x System reset button	F1~F5 function key 1 x Power button 2 x Brightness/volume control 1 x System reset button	F1~F4 function key (2 x brightness/ 2 x volume control) 1 x Shift key 1 x Power button 1 x System reset button
	Video Out	N/A	N/A	1 x HDMI	N/A
	Video Input	N/A	N/A	N/A	4 x CVBS
Expansion	Audio	1 x Mic-in, 1 x Line-out	1 x Mic-in, 1 x Line-out	1 x Mic-in, 1 x Line-out	1 x Mic-in, 1 x Line-out
	Ethernet	1 x Intel® 10/100/1000	1 x Intel® 10/100/1000	1 x Intel® 10/100/1000/2500	1 x Intel® 10/100/1000 (M12)
	PoE	N/A	N/A	N/A	N/A
	USB	3 x USB 2.0	1 x USB 3.2 (Gen1)	1 x USB 3.2 (Gen2)	3 x USB 2.0
	COM	1 x RS232 (Full), 1 x RS232/485	1 x RS232 (Full), 1 x RS232 (Tx, Rx) or 1 x RS485	1 x RS232 (Full)/RS422/RS485 1 x RS232, 1 x RS485	1 x RS232 (Full), 1 x RS232, 1 x RS232/RS422/RS485
Environment	DIO	3 x DI, 3 x DO	2 x PWM, 2 x AI, 2 x DI, 2 x DO	3 x DI, 2 x DO	1 x PWM, 1 x Direction, 2 x DI, 2 x DO
	CAN	2 x CAN Bus 2.0B (w/o isolation)	2 x CAN Bus 2.0B (w/o isolation)	1 x CAN FD (w/ isolation)	1 x CAN Bus 2.0B (w/ isolation)
	SIM Socket	1	1	1	2
	WWAN	1	1	1	1
	mini-PCIe Socket	- 1 x (USB 2.0, PCIe 2.0) - 1 x (USB 2.0) for LTE	- 1 x (USB 2.0, PCIe 2.0) - 1 x (USB 2.0) for LTE	N/A	N/A
Others	M.2 Socket	N/A	N/A	- 1 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen2), SATA 3.0) for LTE/5G - 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0x2). BOM option to 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0, PCIe 3.0) - 1 x M.2 2242 Key B (USB 2.0, PCIe 3.0/SATA 3.0 (auto detect))	- 1 x M.2 2230 Key E (PCIe 2.0, SDIO 3.0, UART) - 1 x M.2 3042/3050/3052 Key B (USB 3.2 (Gen1)) for LTE/5G
	GNSS	Onboard u-blox NEO-M8N	Onboard u-blox NEO-M8N	VI0B-GPS-07 module (u-blox NEO-M9N)	VI0B-GPS-02 module (u-blox NEO-M8N)
	Power Input	DC 9V to 36V	DC 9V to 36V	DC 9V to 36V	DC 9V to 60V
	Back Up Battery	N/A	N/A	N/A	N/A
	Ingress Protection	Front panel IP54	Front panel IP54	Front panel IP54	IP65
Others	Certification	CE, FCC Class B, UKCA, E13	CE, FCC Class B, UKCA, E13, SAE J1113, SAE J1455, ISO7637-2, EN 60950-1 LVD	CE, FCC Class B, UKCA, E13	CE, FCC Class B, UKCA, E13, IK08
	Operating Temperature	-20°C to 70°C	-20°C to 60°C	-30°C to 60°C	-40°C to 70°C
	TPM	N/A	N/A	TPM 2.0	TPM 2.0, optional
OS	Android 5.1	Win 7/8/10, WES 7/8, Linux (Kernel 4.x)	Win 10/11, Linux (Kernel 4.x)	Linux (Kernel 5.4.47)	
Mounting	VESA 75	VESA 75	VESA 75	VESA 75	
Dimensions (mm)	213.0 x 145.0 x 40.0	213.0 x 145.0 x 50.0	213.0 x 145.0 x 50.0	250.0 x 179.0 x 68.0	



Vehicle Mount Computer

Model	 VMC 320-AC0	 VMC 2020-PC1	 VMC 3020
Display	LCD Size: 10.1" TFT LCD Resolution: 1280 x 800 Brightness (Typ.): 1000cd/m ² Contrast Ratio: 800:1 View Angle: V: 85/85 H: 85/85 Brightness Adjustment: Auto via light sensor Touch Screen: Projected capacitive, anti-glare	LCD Size: 8" TFT LCD Resolution: 1280 x 720 Brightness (Typ.): 1000cd/m ² Contrast Ratio: 1000:1 View Angle: V: 85/85 H: 85/85 Brightness Adjustment: Auto via light sensor Touch Screen: Projected capacitive, anti-glare	LCD Size: 10.4" TFT LCD Resolution: 1024 x 768 Brightness (Typ.): 1200cd/m ² Contrast Ratio: 900:1 View Angle: V: 85/85 H: 85/85 Brightness Adjustment: Auto via light sensor Touch Screen: 5-wire resistive, anti-glare
System	CPU: NXP i.MX 8M Plus, 4-core, 1.6GHz Chipset: N/A Memory: 1 x LPDDR4 2133 SDRAM, 3GB onboard Storage: 1 x 16GB eMMC 5.1, 1 x Micro SDXC	CPU: Intel Atom® x7-E3950, 4-core, 1.6GHz Chipset: N/A Memory: 1 x DDR3L 1866 SO-DIMM, 4GB (default) up to 8GB Storage: 1 x 64GB eMMC 5.1, 1 x mSATA (occupied mini-PCIe socket)	CPU: Intel Atom® x5-E3930, 2-core, 1.3GHz Chipset: N/A Memory: 1 x DDR3L 1866 SO-DIMM slot, 4GB (default) up to 8GB Storage: 1 x CFast, 1 x 2.5" SATA 3.0 SSD bay (9.5mm)
I/O Interface	Speaker: 2 x Built-in speaker Control Button: F1~F5 function key (2 x brightness/ 2 x volume control, 1 x mute), 1 x Power button, 1 x System reset button Video Out: 1 x HDMI Video Input: N/A Audio: 1 x Mic-in, 1 x Line-out Ethernet: 1 x Intel® 10/100/1000 (M12) PoE: N/A USB: 2 x USB 2.0, 1 x USB 3.2 (Gen1) COM: 2 x RS232 (full)/422/485 DIO: 2 x DI, 2 x DO CAN Bus: 1 x CAN FD (w/ isolation) SIM Socket: 2 WWAN: 1 mini-PCIe Socket: N/A	Speaker: 2 x Built-in speaker Control Button: F1~F4 function key (2 x brightness/ 2 x volume control), 1 x Shift key, 1 x Power button, 1 x System reset button Video Out: N/A Video Input: 4 x CVBS (optional) Audio: 1 x Mic-in, 1 x Line-out Ethernet: 1 x Intel® 10/100/1000 (M12) PoE: N/A USB: 1 x USB 3.2 (Gen1), 2 x USB 2.0 COM: 1 x RS232 (full), 1 x RS232, 1 x RS232/RS422/RS485 DIO: 1 x PWM, 1 x Direction, 2 x DI, 2 x DO CAN Bus: 1 x CAN Bus 2.0B (w/ isolation) SIM Socket: 2 WWAN: 1 mini-PCIe Socket: - 1 x (USB 2.0, PCIe 2.0), - 1 x (USB 2.0, PCIe 2.0/SATA 3.0)	Speaker: 2 x Built-in speaker Control Button: 1 x Power button, 2 x Brightness control, 2 x Volume control, 5 x Function key, 1 x Shift key Video Out: N/A Video Input: N/A Audio: 1 x Mic-in, 1 x Line-out Ethernet: 1 x Intel® 10/100/1000 PoE: N/A USB: 2 x USB 2.0 (5V/0.5A), 1 x Power USB (5V/1.5A, 12V/1.5A) COM: 2 x Powered RS232 (full, 5V/1.5A, 12V/1.5A) DIO: 2 x DI, 2 x DO CAN Bus: 1 x CAN Bus 2.0B (w/ isolation) SIM Socket: 1 WWAN: 1 mini-PCIe Socket: - 1 x (USB 2.0, PCIe 2.0), - 1 x (USB 2.0) for LTE
Expansion	M.2 Socket: - 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0), - 1 x M.2 3042/3050/3052 Key B (USB 3.2 (Gen1)) for LTE/5G	M.2 Socket: - 1 x M.2 3042/3050/3052 Key B (USB2.0, USB 3.2 (Gen1)) for LTE/5G	M.2 Socket: - 1 x M.2 2230 Key E (USB 2.0, PCIe 2.0, SDIO 3.0, UART)
Power Environment	GNSS: VIOB-GPS-06 module (u-blox NEO-M9N) Power Input: DC 9V to 60V Back Up Battery: Optional Ingress Protection: Front panel IP65 Certification: CE, FCC Class B, UKCA, E13 Operating Temperature: -30°C to 70°C TPM: TPM 2.0	GNSS: VIOB-GPS-02 module (u-blox NEO-M8N) Power Input: DC 9V to 60V Back Up Battery: N/A Ingress Protection: IP65 Certification: CE, FCC Class B, UKCA, E13, IK08 Operating Temperature: -30°C to 60°C TPM: TPM 2.0, optional	GNSS: Optional Power Input: DC 9V to 60V Back Up Battery: Optional Ingress Protection: Front panel IP65 Certification: CE, FCC Class B, UKCA, E13 Operating Temperature: -30°C to 60°C TPM: N/A
Others	OS: Linux (Kernel 5.15.71) Mounting: VESA 75/100 Dimensions (mm): 294.0 x 227.5 x 37.2	OS: Win 10, Linux (Kernel 4.x) Mounting: VESA 75 Dimensions (mm): 250.0 x 179.0 x 68.0	OS: Win 10, Linux (Kernel 4.x) Mounting: VESA 75/100 Dimensions (mm): 290.0 x 230.0 x 68.0



Model	 VMC 3021	 VMC 3030-AC0	 VMC 4020-4A0	 VMC 4020-4A1
Display	LCD Size: 10.4" TFT LCD Resolution: 1024 x 768 Brightness (Typ.): 1200cd/m ² Contrast Ratio: 900:1 View Angle: V: 85/85 H: 85/85 Brightness Adjustment: Auto via light sensor Touch Screen: 5-wire resistive, anti-glare	LCD Size: 10.1" TFT LCD Resolution: 1280 x 800 Brightness (Typ.): 1000cd/m ² Contrast Ratio: 800:1 View Angle: V: 85/85 H: 85/85 Brightness Adjustment: Auto via light sensor Touch Screen: Projected capacitive, anti-glare	LCD Size: 12.1" TFT LCD Resolution: 1024 x 768 Brightness (Typ.): 1200cd/m ² Contrast Ratio: 750:1 View Angle: V: 85/85 H: 85/85 Brightness Adjustment: Auto via light sensor Touch Screen: 5-wire resistive, anti-glare	LCD Size: 12.1" TFT LCD Resolution: 1024 x 768 Brightness (Typ.): 1200cd/m ² Contrast Ratio: 750:1 View Angle: V: 85/85 H: 85/85 Brightness Adjustment: Auto via light sensor Touch Screen: 5-wire resistive, anti-glare
System	CPU: Intel Atom® x7-E3950, 4-core, 1.6GHz Chipset: N/A Memory: 1 x DDR3L 1866 SO-DIMM slot, 4GB (default) up to 8GB Storage: 1 x CFast, 1 x 2.5" SATA 3.0 SSD bay (9.5mm)	CPU: Intel Atom® x7433RE, 4-core, 1.5GHz Chipset: N/A Memory: 1 x DDR5 4800 SO-DIMM slot, 4GB (default) up to 16GB Storage: 1 x M.2 2280 Key M (SATA 3.0), 1 x Micro SDXC (BOM optional)	CPU: Intel Atom® x7-E3950, 4-core, 1.6GHz Chipset: N/A Memory: 1 x DDR3L 1866 SO-DIMM slot, 4GB (default) up to 8GB Storage: 1 x CFast, 1 x 2.5" SATA 3.0 SSD bay (9.5mm)	CPU: Intel Atom® x7-E3950, 4-core, 1.6GHz Chipset: N/A Memory: 1 x DDR3L 1866 SO-DIMM slot, 4GB (default) up to 8GB Storage: 1 x CFast, 1 x 2.5" SATA 3.0 SSD bay (9.5mm)
I/O Interface	Speaker: 2 x Built-in speaker Control Button: 1 x Power button, 2 x Brightness control, 2 x Volume control, 5 x Function key, 1 x Shift key Video Out: N/A Video Input: 3 x CVBS Audio: 1 x Mic-in, 1 x Line-out Ethernet: 1 x Intel® 10/100/1000 (M12) PoE: 1 x (802.3af/at), Total 30W (optional) USB: 2 x USB 2.0 COM: 1 x RS232 (full)/422/485, 1 x RS232/422/485 DIO: 2 x DI, 2 x DO CAN Bus: 2 x CAN Bus 2.0B (w/ isolation) SIM Socket: 1 WWAN: 1 mini-PCIe Socket: - 3 x (USB 2.0, PCIe 2.0), - 1 x (USB 2.0) for LTE	Speaker: 2 x Built-in speaker Control Button: F1~F5 function key (2 x brightness/ 2 x volume control, 1 x mute), 1 x Power button, 1 x System reset button Video Out: 1 x HDMI Video Input: N/A Audio: 1 x Mic-in, 1 x Line-out Ethernet: 1 x Intel® 10/100/1000/2500 (M12) PoE: N/A USB: 1 x USB 2.0, 2 x USB 3.2 (Gen2) COM: 2 x RS232 (full)/422/485 DIO: 2 x DI, 2 x DO CAN Bus: 1 x CAN FD (w/ isolation) SIM Socket: 2 WWAN: 1 mini-PCIe Socket: - 1 x (USB 2.0, PCIe 3.0/SATA 3.0), - 1 x (USB 2.0) for LTE	Speaker: 2 x Built-in speaker Control Button: 1 x Power button, 2 x Brightness control, 2 x Volume control, 5 x Function key, 1 x Shift key Video Out: N/A Video Input: 3 x CVBS Audio: 1 x Mic-in, 1 x Line-out Ethernet: 2 x Intel® 10/100/1000 PoE: 1 x (802.3af/at), Total 30W (optional) USB: 2 x USB 2.0 COM: 2 x RS232 (full)/422/485 DIO: 1 x DI, 2 x DO CAN Bus: 2 x CAN Bus 2.0B (w/ isolation) SIM Socket: 2 WWAN: 1 mini-PCIe Socket: - 3 x (USB 2.0, PCIe 2.0), - 1 x (USB 2.0) for LTE	Speaker: 2 x Built-in speaker Control Button: 1 x Power button, 2 x Brightness control, 2 x Volume control, 5 x Function key, 1 x Shift key Video Out: N/A Video Input: 3 x CVBS Audio: 1 x Mic-in, 1 x Line-out Ethernet: 2 x Intel® 10/100/1000 (M12) PoE: 1 x (802.3af/at), Total 30W (optional) USB: 3 x USB 2.0 COM: 1 x RS232 (full)/422/485, 1 x RS232 (Tx, Rx)/422/485 DIO: 2 x DI, 2 x DO CAN Bus: 2 x CAN Bus 2.0B (w/ isolation) SIM Socket: 2 WWAN: 1 mini-PCIe Socket: - 3 x (USB 2.0, PCIe 2.0), - 1 x (USB 2.0) for LTE
Expansion	M.2 Socket: N/A	M.2 Socket: - 1 x M.2 3042/3050/3052 Key B (USB 2.0, USB 3.2 (Gen2)) for LTE/5G, - 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0 x2), BOM option to 1 x M.2 2230 Key E (USB 2.0, PCIe 3.0, PCIe 3.0)	M.2 Socket: N/A	M.2 Socket: N/A
Power Environment	GNSS: VIOB-GPS-02 module (u-blox NEO-M8N) Power Input: DC 9V to 60V Back Up Battery: Optional Ingress Protection: IP65 Certification: CE, FCC Class B, UKCA, E13 Operating Temperature: -30°C to 60°C TPM: N/A	GNSS: VIOB-GPS-06 module (u-blox NEO-M9N) Power Input: DC 9V to 60V Back Up Battery: Optional Ingress Protection: Front panel IP65 Certification: CE, FCC Class B, UKCA, E13 Operating Temperature: -30°C to 60°C TPM: TPM 2.0	GNSS: VIOB-GPS-02 module (u-blox NEO-M8N) Power Input: DC 9V to 60V Back Up Battery: Optional Ingress Protection: Front panel IP65 Certification: CE, FCC Class B, UKCA, E13 Operating Temperature: -30°C to 60°C TPM: N/A	GNSS: VIOB-GPS-02 module (u-blox NEO-M8N) Power Input: DC 9V to 60V Back Up Battery: Optional Ingress Protection: IP65 Certification: CE, FCC Class B, UKCA, E13 Operating Temperature: -30°C to 60°C TPM: N/A
Others	OS: Win 10, Linux (Kernel 4.x) Mounting: VESA 75/100 Dimensions (mm): 290.0 x 230.0 x 68.0	OS: Win 10/11, Linux (Kernel 4.x) Mounting: VESA 75/100 Dimensions (mm): 294.0 x 227.5 x 54.0	OS: Win 10, Linux (Kernel 4.x) Mounting: VESA 75/100 Dimensions (mm): 340.0 x 262.0 x 75.0	OS: Win 10, Linux (Kernel 4.x) Mounting: VESA 75/100 Dimensions (mm): 340.0 x 262.0 x 75.0



Vehicle Mount Display

Model				
	VMD 1001	VMD 2000	VMD 2002	
Display	LCD Size	7" TFT LCD	8" TFT LCD	8" TFT LCD
	Resolution	800 x 480	800 x 600	800 x 600
	Brightness (Typ.)	500cd/m²	500cd/m²	500cd/m²
	Contrast Ratio	600:1	500:1	500:1
	View Angle	V: 60/60 H: 70/70	V: 50/70 H: 70/70	V: 50/70 H: 70/70
	Brightness Adjustment	Auto via light sensor	Auto via light sensor	Auto via light sensor
	Touch Screen	4-wire resistive, anti-glare	4-wire resistive, anti-glare	4-wire resistive, anti-glare
I/O Interface	Speaker	2 x Built-in speaker	2 x Built-in speaker	2 x Built-in speaker
	Camera	N/A	N/A	N/A
	Control Button	1 x Monitor power button 2 x Brightness control 2 x Volume control	1 x Monitor power button 2 x Brightness control 2 x Volume control	1 x Monitor power button 2 x Brightness control 2 x Volume control
	Video Input	VGA	Integrated LVDS CONN (LVDS, USB, 12V)	Integrated DVI CONN (VGA, USB, 12V)
	Audio	1 x Line-in (lateral side) 1 x Line-out (lateral side)	1 x Line-out (lateral side) 1 x Mic-in (lateral side) 1 x Line-in (bottom side) 1 x Mic-out (bottom side)	1 x Line-out (lateral side) 1 x Mic-in (lateral side) 1 x Line-in (bottom side) 1 x Mic-out (bottom side)
	USB	2 x USB 2.0	1 x USB 2.0	1 x USB 2.0
	Remote Power Button	N/A	Remotely power on/off VTC, MVS & ATC	N/A
Power/ Environment	Power Input	DC 9V to 36V	DC 12V (via LVDS)	DC 9V to 36V
	Ingress Protection	Front panel IP54	Front panel IP54	Front panel IP54
	Certification	CE, FCC Class B, UKCA	CE, FCC Class B, UKCA	CE, FCC Class B, UKCA
	Operating Temperature	-20°C to 70°C	-20°C to 60°C	-20°C to 60°C
Others	Mounting	VESA 75	VESA 75	VESA 75
	Dimensions (mm)	182.0 x 138.0 x 36.3	207.0 x 173.0 x 36.7	207.0 x 173.0 x 36.7



Model					
	VMD 2003	VMD 3002-BS2	VMD 3110	VMD 3111	
Display	LCD Size	8" TFT LCD	10.4" TFT LCD	10.4" TFT LCD	
	Resolution	800 x 600	1024 x 768	1024 x 768	
	Brightness (Typ.)	1000cd/m²	1200cd/m²	1200cd/m²	
	Contrast Ratio	500:1	900:1	900:1	
	View Angle	V: 60/60 H: 70/70	V: 85/85 H: 85/85	V: 85/85 H: 85/85	
	Brightness Adjustment	Auto via light sensor	Auto via light sensor	Auto via light sensor	
	Touch Screen	4-wire resistive, anti-glare	Projected capacitive	Projected capacitive	
I/O Interface	Speaker	2 x Built-in speaker	2 x Built-in speaker	2 x Built-in speaker	
	Camera	N/A	N/A	N/A	
	Control Button	1 x Monitor power button 2 x Brightness control 2 x Volume control	1 x Monitor power button 1 x OSD menu 2 x Brightness control 2 x Volume control 1 x Auto config	1 x Monitor power button 1 x OSD menu 2 x Brightness control 2 x Volume control 1 x Auto config	1 x Monitor power button 1 x OSD menu 2 x Brightness control 2 x Volume control 1 x Auto Config
	Video Input	ultraONE+, 4 x CVBS	VGA, 4 x CVBS	ultraONE+, 4 x CVBS	HDMI
	Audio	1 x Line-out (lateral side) 1 x Mic-in (lateral side)	1 x Line-in	1 x Line-in	via HDMI
	USB	1 x USB 2.0	1 x USB 2.0	1 x USB 2.0	1 x USB 2.0
	Remote Power Button	Remotely power on/off VTC, MVS & ATC	N/A	Remotely power off VTC, MVS & ATC	N/A
Power/ Environment	Power Input	DC 24V (via ultraONE+)	DC 9V to 36V	DC 24V (via ultraONE+)	
	Ingress Protection	Front panel IP54	IP65	IP65	
	Certification	CE, FCC Class B, UKCA	CE, FCC Class B, UKCA	CE, FCC Class B, UKCA	
	Operating Temperature	-20°C to 60°C	-20°C to 60°C	-20°C to 60°C	
Others	Mounting	VESA 75	VESA 75/100	VESA 75/100	
	Dimensions (mm)	207.0 x 173.0 x 36.7	256.5 x 202.1 x 31.5	256.5 x 202.1 x 31.5	



Coming soon

Add-on Modules and Devices

Model						
Description	CAN Bus 2.0B or OBD SAE J1939 module	Dual CAN Bus 2.0B module	SAE J1708 module	OBD SAE J1939 module	u-blox M8N module	u-blox M9N module
Input I/F	UART	USB 2.0	USB 2.0	USB 2.0	UART	UART
Input Connector	2 x 5-pin wafer	mini-PCIe Socket	mini-PCIe Socket or USB wafer	mini-PCIe Socket or USB wafer	6-pin wafer	6-pin wafer
Output I/F	CAN Bus 2.0B or OBD SAE J1939	2 x CAN Bus 2.0B	SAE J1708/J1587/J1922	OBD SAE J1939	UART	UART
Output Connector	2 x 5-pin wafer	6-pin wafer to DB9	3-pin wafer to DB9	3-pin wafer to DB9	6-pin wafer	6-pin wafer
Operating Temperature	-40°C to 85°C	-40°C to 85°C				
Form Factor	Proprietary	Full-Size mini-PCIe	Full-Size mini-PCIe	Full-Size mini-PCIe	Proprietary	Proprietary
Dimensions (mm)	50.0 x 28.0	51.0 x 30.0	51.0 x 30.0	51.0 x 30.0	25.4 x 25.4	25.4 x 25.4
Remark	* CAN Bus 2.0B & SAE J1939 selection by switch	-	-	-	*Baud Rate: 9600. u-blox NEO-M8N GNSS supports with GPS + QZSS, GLONASS, Galileo and BeiDou. 3 of concurrent GNSS	*Baud Rate: 38400. u-blox NEO-M9N GNSS supports with GPS + QZSS/SBAS, GLONASS, Galileo and BeiDou. 4 of concurrent GNSS

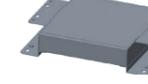


Model							
Description	u-blox M9N module	u-blox M9N module	u-blox M8L module	u-blox M9V module	u-blox M9V module	M.2 to mini-PCIe converter module	
Input I/F	USB2.0	UART/USB2.0	UART	UART	UART/USB2.0	USB 2.0, USB 3.0	
Input Connector	6-pin wafer	8-pin wafer	6-pin wafer	6-pin wafer	8-pin wafer	M.2 Key B + M	
Output I/F	UART	UART/USB2.0	UART	UART	UART/USB2.0	mini-PCIe	
Output Connector	6-pin wafer	8-pin wafer	6-pin wafer	6-pin wafer	8-pin wafer	mini-PCIe (socket)	
Operating Temperature	-40°C to 85°C	-40°C to 85°C	-40°C to 85°C	-40°C to 85°C	-40°C to 85°C	-40°C to 85°C	
Form Factor	Proprietary	Proprietary	Proprietary	Proprietary	Proprietary	M.2 3042/3052 Key B + M	
Dimensions (mm)	25.4 x 25.4	25.4 x 25.4	25.4 x 25.4	25.4 x 25.4	25.4 x 25.4	62.0 x 31.0	
Remark	*Baud Rate: 38400. u-blox NEO-M9N GNSS supports with GPS + QZSS/SBAS, GLONASS, Galileo and BeiDou. 4 of concurrent GNSS	*Baud Rate: 38400. u-blox NEO-M9N GNSS supports with GPS + QZSS/SBAS, GLONASS, Galileo and BeiDou. 4 of concurrent GNSS	*Baud Rate: 9600. u-blox NEO-M8L-06B GNSS supports with GPS, GLONASS, Galileo, BeiDou and QZSS * Automotive Dead Reckoning (ADR) * With battery	*Baud Rate: 38400. u-blox NEO-M9V-20B GNSS supports with GPS, GLONASS, Galileo, BeiDou and QZSS * Support ADR and UDR * With battery	*Baud Rate: 38400. u-blox NEO-M9V-20B GNSS supports with GPS, GLONASS, Galileo, BeiDou and QZSS * Support ADR and UDR * With battery	-	Only for LTE module



Model					
Description	mini-PCIe to M.2 converter module	mini-PCIe to M.2 converter module	2 x Mic-in & 2 x Line-out module	External attachable power isolation kit	5G/Wi-Fi expansion board
Input I/F	USB 2.0, USB 3.2 (Gen1)	USB 2.0, PCIe 3.0	USB 2.0	VTK 6222-APK: DC 24V VTK 6222-FPK: DC 110V	1 x PCIe 3.0 x4, 2 x PCIe 3.0 x2, 2 x USB 3.2 Gen 1, 2 x USB 2.0
Input Connector	mini-PCIe	mini-PCIe	mini-PCIe or USB wafer	M12 (5-pin)	Board to board connector
Output I/F	M.2 Key B	M.2 Key E	2x Line-out & 2x Mic-in	24VDC	N/A
Output Connector	M.2 (socket)	M.2 (socket)	1 x 10-pin wafer to DB15	M12 (5-pin)	- 1 x Full size mini-PCIe socket (USB 2.0, PCIe 3.0), BOM optional M.2 2230 Key E socket (USB 2.0, PCIe 3.0) - 2 x M.2 3042/3050/3052 Key B socket (USB 2.0, USB 3.2 Gen 1) for LTE/5G NR module with 1 x external dual nano-SIMs
Operating Temperature	-40°C to 85°C	-40°C to 85°C	-40°C to 85°C	-40°C to 70°C	-40°C to 70°C
Form Factor	Full-Size mini-PCIe	Full-Size mini-PCIe	Full-Size mini-PCIe	Proprietary	Proprietary
Dimensions (mm)	65.0 x 30.0	51.0 x 30.0	51.0 x 30.0	120.0 x 198.0 x 50.0	234.0 x 72.0
Remark	USB 3.2 (Gen1) depended by mainbord	-	-	Only for nROK6222	Only for nROK7270/ nROK7271



Model						
Description	PoE expansion board	10GbE expansion board	External attachable power isolation kit	Vehicle relay module	Smart backup battery kit	Smart UPS with SuperCap
Input I/F	1 x PCIe 3.0 x4, 2 x PCIe 3.0 x2, 2 x USB 3.2 Gen 1, 2 x USB 2.0	1 x PCIe 3.0 x4, 2 x PCIe 3.0 x2, 2 x USB 3.2 Gen 1, 2 x USB 2.0	DC 24V	USB 2.0 or RS-232 (Tx/Rx)	DC 9V to 36V	DC 9V to 60V
Input Connector	Board to board connector	Board to board connector	VTK PWA20-01: K-coded; VTK PWA10-01: A-coded (M12, 5-pin)	USB type A or DB9	3-pin terminal block	5-pin terminal block
Output I/F	N/A	N/A	24VDC	4 x Relay 4 x DI 4 x DO 1 x Analog input 1 x Frequency input	10-12VDC (from backup battery) 9-36VDC (from vehicle battery) Communication: RS232/SMbus	12/24VDC (from backup SuperCap) 9-60VDC (from vehicle battery) Communication: RS232
Output Connector	8-port M12 X-coded, 10/100/1000 Mbps, PoE 802.3 af/at	- 2-port 10GbE M12 X-coded - 1 x M.2 3042/3050/3052 Key B socket (USB 2.0, USB 3.2 Gen 1) for LTE/5G NR module with 2 x external dual nano-SIMs - 1 x Full size mini-PCIe socket (USB 2.0, PCIe 3.0), BOM optional 1 x M.2 3042/3050/3052 Key B socket (USB 2.0, USB 3.2 Gen 1) for LTE/5G NR module with 2 x external dual nano-SIMs	A-coded (M12, 5-pin)	Terminal block	Power: 3 Pin terminal block Communication: 2 x 5-pin	Power: 6 Pin terminal block Communication: DB9
Operating Temperature	-40°C to 70°C	-40°C to 70°C	-40°C to 70°C	-40°C to 85°C	Charging: 0°C to 45°C Discharging: 0°C to 55°C	Charging: -35°C to 80°C Discharging: -40°C to 80°C
Form Factor	Proprietary	Proprietary	Proprietary	Proprietary	Proprietary	Proprietary
Dimensions (mm)	234.0 x 72.0	234.0 x 72.0	VTK PWA20-01: 234.1 (W) x 172.8 (D) x 40.0 (H) VTK PWA10-01: 213 (W) x 167.0 (D) x 40.0 (H)	126.0 (W) x 124.0 (D) x 24.0 (H)	(1) 280.0 (W) x 150.0 (D) x 42.2 (H) (w/ VTK-62B1-BK) (2) 297.3 (W) x 175.0 (D) x 39.0 (H) (w/ VTK-62B2-BK)	235.0 (W) x 134.5 (D) x 50.0 (H)
Remark	Only for nROK7270/ nROK7271	Only for nROK7270/ nROK7271	VTK PWA20-01 for ATC 3750-C6 VTK PWA10-01 for ATC 3530-IP7-C4	It is remotely controlled through USB or RS-232 communication.	Capacity: 9000 mAh (Li-Ion) 60W output	Nominal 24V [®] 8A max (200W, 1 x master + 3 x slave) For in-vehicle, VTK-SCAP-M (master), VTK-SCAP-S (slave) For Railway, VTK-SCAP-AR-M (master), VTK-SCAP-S (slave)



HDMI over IP Extender

VIP Series Brief Product Introduction

Product Description

VIP Series is a new E-Mark certified in-vehicle HDMI extender over IP solution designed with 9~36VDC wide voltage input range, specifically for railway and bus public transport Passenger infotainment System.

VIP Series works over standard networking devices with wide operating temperature support, and outputs to multiple Full HD HDMI displays up to 100m.

 Wide-range 9-36Vdc input voltage

 Unicast and daisy chain support

 E-Mark for in-vehicle application

 Dual Full HD HDMI output

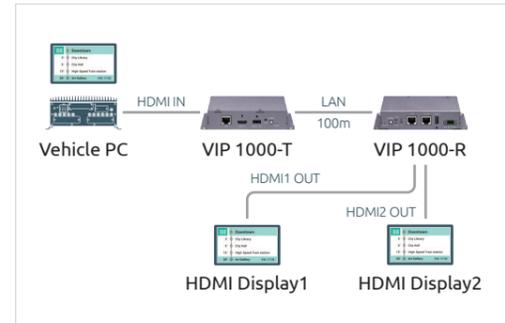
Application

- Video on demand
- Passenger infotainment system

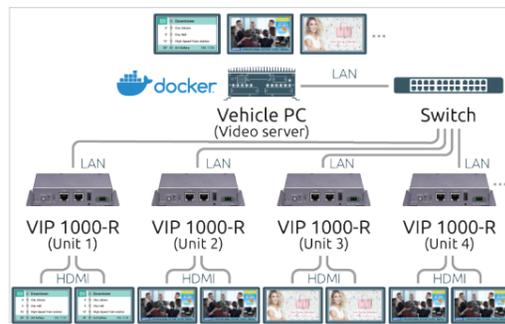
Product Highlight



Dedicated for in-vehicle & railway PIS application



Support dual Full HD HDMI output + Up to 100 meter distance



RTSP video on demand with Docker platform



Easy to use. Plug and play!

Model	 VIP 1000-T	 VIP 1000-R
Function	Transmitter	Receiver
Video In	1 x HDMI	1 x 10/100/1000
Video Out	1 x 10/100/1000	2 x HDMI
Protocol	TCP/IP	TCP/IP
Model	Unicast, daisy chain and multicast mode	Unicast, daisy chain and multicast mode
USB	1 x USB 2.0 OTG	1 x USB 2.0
Ethernet	1 x 10/100/1000	2 x Intel® 10/100/1000
Power Input	DC 9V to 36V	DC 9V to 36V
Ignition Control	Yes	Yes
Certification	CE, FCC Class A, UKCA, E13	CE, FCC Class A, UKCA, E13
Operating Temperature	-20°C to 70°C	-20°C to 70°C
Dimensions (mm)	130.0 x 100.0 x 31.0	130.0 x 100.0 x 31.0



About NEXCOM

Reliable Partner for the AIoT Digital Transformation Solutions

Committed to Customer Success

Founded in 1992 and headquartered in Taipei, Taiwan, NEXCOM is committed to being a trustworthy partner in building the AIoT digital transformation solutions. To surpass customers' expectations, NEXCOM sets itself apart by leveraging its decades of experience in industrial computing, a highly talented R&D team, and exceptional customer service. With these core strengths, NEXCOM has enabled its customers to win key projects in a diverse range of industries.

With its focus on delivering these core values to better serve customers, NEXCOM integrates its capabilities and operates six global businesses: IoT Automation Solutions (IAS), Intelligent Video Surveillance (IDS), Intelligent Platform @ Smart City (IPS), Mobile Computing Solutions

(MCS), Medical & Healthcare Informatics (MHI), Network and Communication Solutions (NCS). This strategic deployment enables NEXCOM to offer time-to-market, time-to-solution products and services without compromising on cost.

In addition, the service-to-market business model gives NEXCOM core competence in building a strong world-class service network by providing customized service, global logistics, local access, and real-time support. Operating six subsidiaries in China, Japan, Taiwan, and the United States, NEXCOM is able to better accommodate customers' requirements as well as closely work with global partners in different regions.

Partners can also be assured that NEXCOM's Taiwan-based Headquarters and subsidiary offices in China and the USA have obtained ISO 9001:2015 Certification.



IAS	IoT Automation Solutions: Industrial Automation & I4.0 Execution, Intelligent Edge, Gateway & EWR, Industrial Robot Control, EtherCAT Motion Solutions, Wireless & Embedded Solutions for Industrial IoT
IDS	Intelligent Video Surveillance: IP Video Surveillance Cameras, Mobile Cameras, ANPR/LPR Network Cameras, Panoramic Cameras, NVR Server Platform
IPS	Intelligent Platform @ Smart City: Smart City, Smart Retail, Digital Signage, Interactive Kiosks, Hospitality, Gateway, Edge AI, and ODM Customization Services
MCS	Mobile Computing Solutions: Edge AI Telematics Computer, Vehicle Telematics Computer, Railway Computer, Vehicle Mount Computer, Vehicle Mount Display, In-Vehicle Networking, In-Vehicle HDMI Extender over IP, Fitness Console
MHI	Medical and Healthcare Informatics: Total Solutions with a Variety of Medical IT Systems
NCS	Network and Communication Solutions: Cyber Security, HPC, Telecommunications, Storage, SDN/NFV, 5G, uCPE, ICS Security

Corporate Vision

To become the industrial leader in providing AIoT digital transformation solutions, NEXCOM utilizes its industry leading technology, localized customer support and worldwide logistics services. This will be achieved by:

- Great team work
- Cooperation with trusted partners
- Growth through innovation

Corporate Mission

- An AIoT digital transformation supplier in vertical application markets
- A quality partner in engineering, manufacturing and services

Business Strategy

Aiming to better support the activities of all its partners, NEXCOM divides its sales force into six dedicated business units to target rapidly expanding vertical markets. This enables each business unit to focus on strategic channel accounts and repeat order business. Moreover, NEXCOM will provide customers with co-marketing strategies, technical support, ODM services, and project support, which are frequently required everywhere.

NEXCOM has already become a business group focused on innovating comprehensive solutions for Industry 4.0. We help our customers deliver vertical solutions optimized for 5G, AI, AIoT, and Industry 4.0 solutions.

Global Fulfillment Service

Product delivery and customer support are always more effective when delivered locally. NEXCOM localizes support and provides a global customer service network to handle all aspects of global business, from presales, order taking, and system assembly to logistics. For expeditious product delivery, NEXCOM has established four regional service centers: Taiwan (for Asia), USA (for North America and South America), and China. Therefore, NEXCOM customers benefit from quality assured product assembly and four service centers.

NEXCOM has invested heavily to establish operational infrastructures, including advanced equipment and facilities, not only at its global headquarters but also at subsidiary offices. Today, each of our service centers, with ISO 9001:2008 certification, has a purpose built assembly line, RMA/ DOA center and warehouse storage capability.

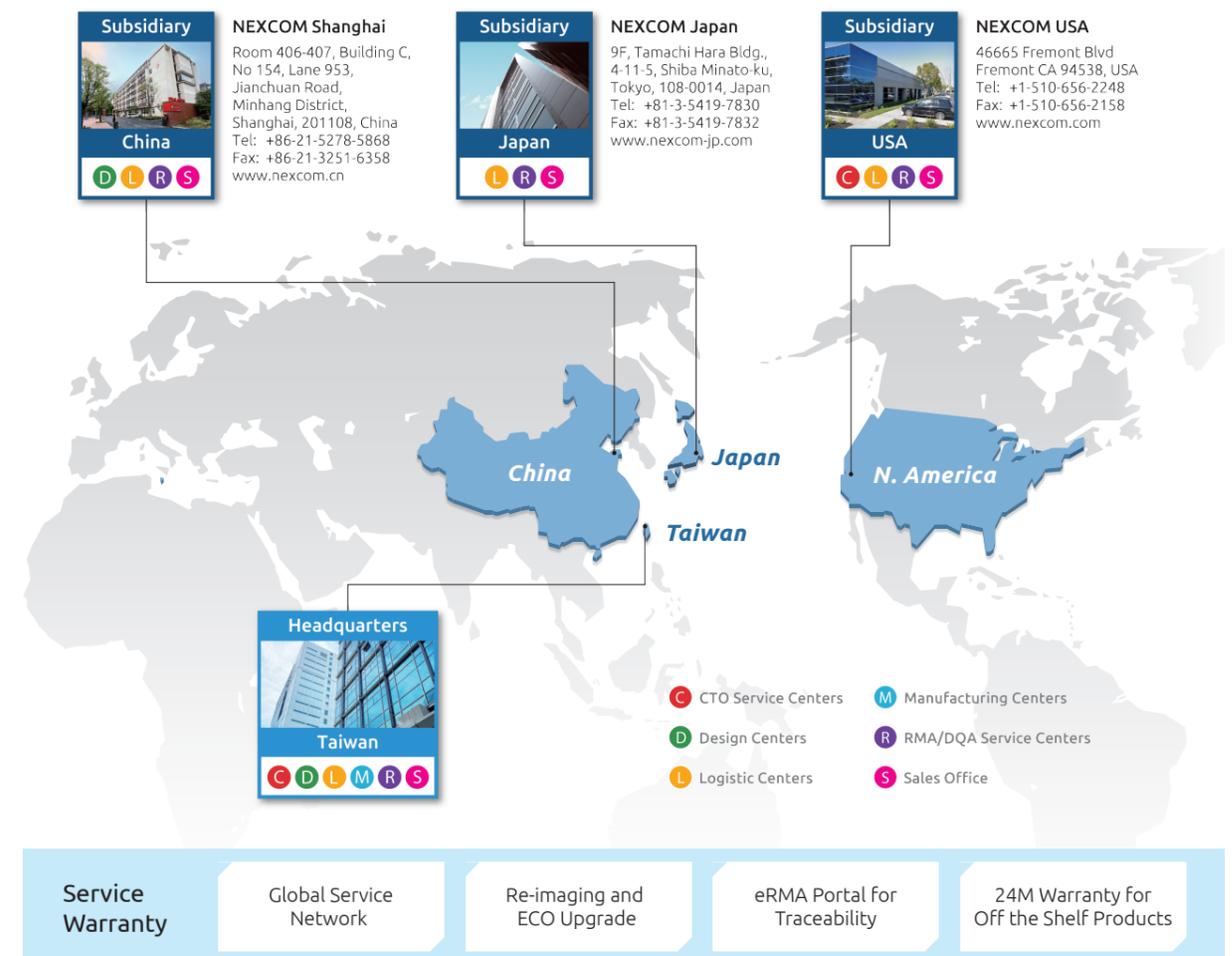
Quality Assurance

Under a strict Quality Assurance System, product design and reliability are controlled to support all critical solutions, and ensure Total Quality Assurance (TQA) implementation for all NEXCOM

products and services. Additionally, NEXCOM's technical support team is aligned with ISO 27001 requirements, as they aim to provide timely feedback within 24 hours to resolve technical issues efficiently. This ensures that any potential information security incidents are addressed promptly, minimizing the impact and downtime for customers.

Green Policy

As a global citizen, NEXCOM places great importance on environmental issues. We are committed to ensuring that our products and services comply with environmental standards and regulations. NEXCOM actively responds to energy-saving and carbon reduction initiatives, prioritizes environmental protection in our operational activities, and holds certificate such as ISO 14064-1 greenhouse gas inventory and ISO 14001 environmental management system. We implement voluntary greenhouse gas inventory, reduce resource and energy consumption, and mitigate environmental risks. We also measure NEXCOM's sustainability and corporate responsibility as an Earth-friendly enterprise through ESG evaluation. NEXCOM will continue to collaborate with peers and suppliers to strive for purification standards, compatibility of technologies, and operational processes to help reduce the potential hazardous substances in our products and manufacturing processes.



Service details may vary by country. Please contact us for more details.

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